

INVESTOR DAY 2018

Tuesday, September, 11, 2018 New York, New York



Public



SECURE CONNECTIONS FOR A SMARTER WORLD

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Welcome Jeff Palmer

VP of Investor Relations





Agenda

8:00 – 8:10am	IR Introduction	Jeff Palmer
8:10 – 8:40am	NXP Overview	Rick Clemmer
8:40 – 9:10am	Financial Overview	Peter Kelly
9:10 – 9:25am	Q&A	Rick Clemmer and P
9:25 – 9:45am	Mobile	Rafael Sotomayor
9:45 – 10:40am	Industrial	Geoff Lees
10:40 – 10:55am	Q&A	Rafael Sotomayor ar
10:55 – 11:10am	Break	
11:10 – 12:40pm	Automotive	Kurt Sievers, Torster
12:40 – 12:55pm	Q&A	Kurt Sievers, Torster
12:55 – 1:10pm	Go-to-Market	Steve Owen
1:10 – 1:30pm	Summary and Q&A	Rick Clemmer and N
1:30 – 2:30pm	Lunch	

Peter Kelly and Geoff Lees

n Lehmann and Jens Hinrichsen n Lehmann and Jens Hinrichsen NXP Management Team





Forward-Looking Statement

This presentation or the subsequent discussion period includes forward-looking statements which include statements regarding our business strategy, financial condition, results of operations, market data and expectations, outlooks, projections, estimates, goals and targets, as well as any other statements which are not historical facts. By their nature, forward-looking statements are subject to numerous factors, risks and uncertainties that could cause actual outcomes and results to be materially different from those projected. These factors, risks and uncertainties include the following: market demand and semiconductor industry conditions, our ability to successfully introduce new technologies and products, the demand for the goods into which our products are incorporated, our ability to generate sufficient cash, raise sufficient capital or refinance our debt at or before maturity to meet both our debt service and research and development and capital investment requirements, our ability to accurately estimate demand and match our production capacity accordingly or obtain supplies from third-party producers, our access to production from thirdparty outsourcing partners, and any events that might affect their business or our relationship with them, our ability to secure adequate and timely supply of equipment and materials from suppliers, our ability to avoid operational problems and product defects and, if such issues were to arise, to rectify them quickly, our ability to form strategic partnerships and joint ventures and successfully cooperate with our alliance partners, our ability to win competitive bid selection processes to develop products for use in our customers' equipment and products, our ability to successfully hire and retain key management and senior product architects; and, our ability to maintain good relationships with our suppliers. In addition, this presentation contains information concerning the semiconductor industry and our business which is forward-looking in nature and is based on a variety of assumptions regarding the ways in which the semiconductor industry, our market segments and product areas will develop. We have based these assumptions on information currently available to us, if any one or more of these assumptions turn out to be incorrect, actual market results may differ from those predicted. While we do not know what impact any such differences may have on our business, if there are such differences, our future results of operations and financial condition, and the market price of the notes, could be materially adversely affected. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak to results only as of the date the statements were made. The forward-looking statements in this presentation are based on management's plans, objectives and information available as of the September 11, 2018 date of this presentation. Except for any ongoing obligation to disclose material information as required by the United States federal securities laws, NXP does not have any intention or obligation to publicly update or revise any forward-looking statements, whether to reflect any future events or circumstances or otherwise. Neither future distribution of this material nor the continued availability of this material in archive form on our website should be deemed to constitute an update or re-affirmation of these forward-looking statements as of any future date. For a discussion of potential risks and uncertainties, please refer to the risk factors listed in our SEC filings. Copies of our filings are available from our Investor Relations department or from the SEC website, www.sec.gov

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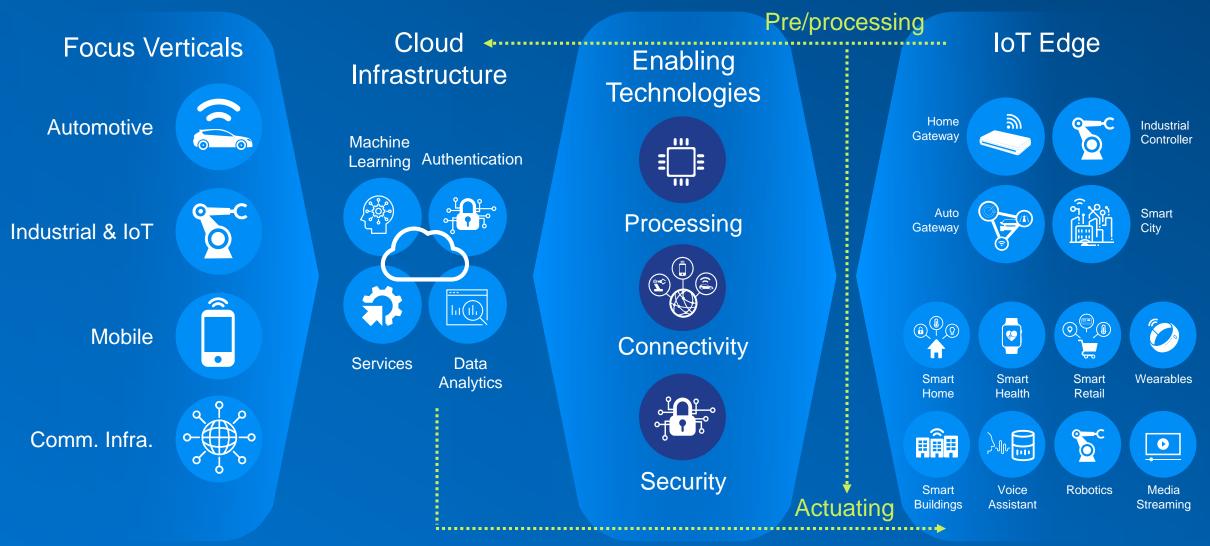
NXP Overview

Rick Clemmer Chief Executive Officer





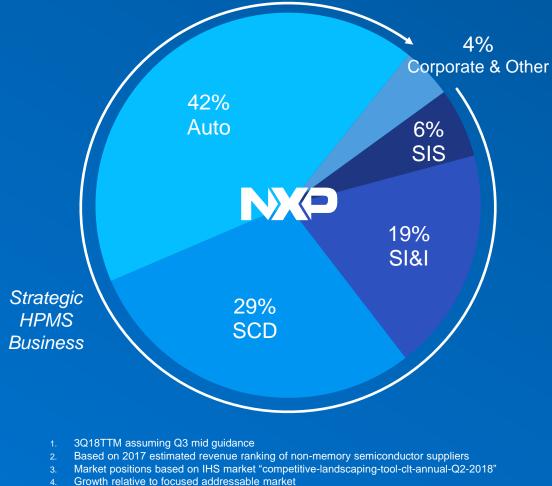
Secure Connections for the Smarter World... has Evolved





HPMS Market Leader with Sharp Focus, Broad Reach12345

NXP 3Q18TTM Revenue by Operating Segment



NXP: the HPMS leader

- #5 global non-memory semi supplier
- #1 global auto semi supplier
- Focused IoT processing: MCU–CrossOver–AP
 #2 MCU supplier
- #1 secure identification

Goal: deliver >1.5x market growth

- Complementary portfolios and customers
- Opportunities to cross sell
- Ability to deliver complete solutions

5. ABI Research Secure Smart Card & Embedded Security IC Technologies, 1Q18

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Addressing 4 Major End Markets



Automotive

ADAS + Electrification System solutions innovation with OEMs Increased content drives growth



Industrial & IoT

Fragmented customer base Processing needs are transforming markets Scalable solutions as a differentiator



Mobile

~2B mobile phone and adjacent device market

Ongoing feature innovation & attach



Communication, Infrastructure & Other

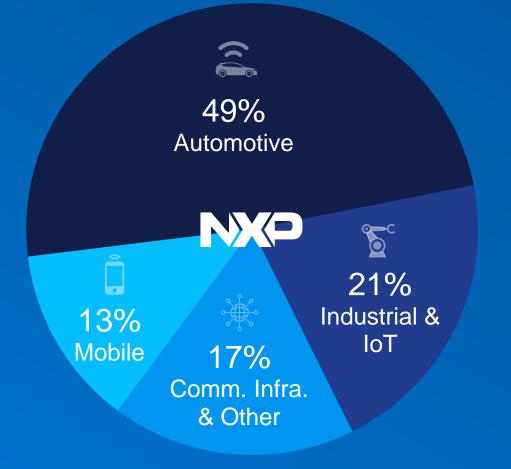
Capex-driven wireless infrastructure market

Secular growth driven by new cellular standard



Focused Leadership – End Markets¹

NXP 3Q18TTM HPMS Revenue by End-market Exposure



Broad end market exposure

- Long product life cycles
- High barriers to entry
- Application expertise

Recognized leadership in

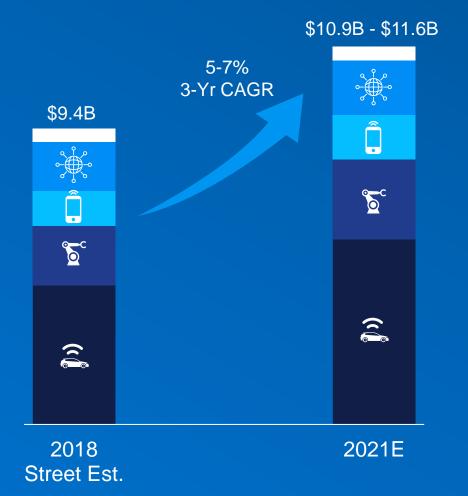
- Automotive
- MCU and application processors
- Mobile transactions
- RF Power amplifiers. mMIMO
- Secure identification, mobility, RFID



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Growth Opportunity Driven by Focus End Markets¹²

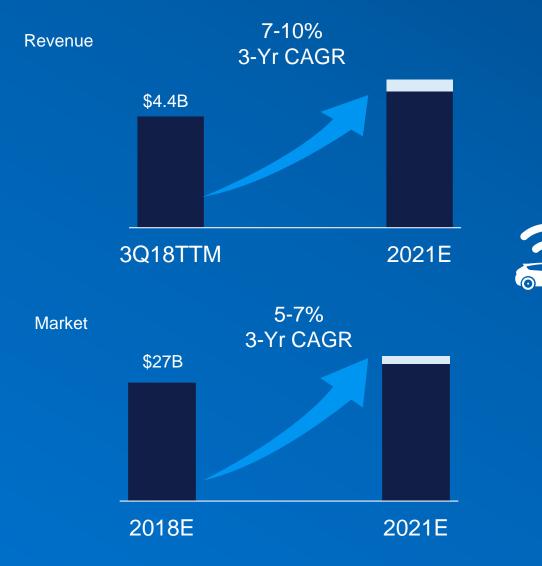
Growth by End Market



End Market	Percent 3Q18TTM Revenue	2018E – 2021E 3-yr. CAGR
Automotive	47%	Up 7 to 10%
Industrial & IoT	20%	Up 8 to 11%
Mobile	12%	Up 4 to 6%
Comm. Infra. & Other	17%	0 to up 2%
Corporate & Other	4%	(3%)
Total	100%	Up 5 - 7%

2. 3Q18 TTM financial data based on 4Q17-3Q18E (mid-point guide)

Automotive – NXP Leads, Accelerates in New Areas¹²

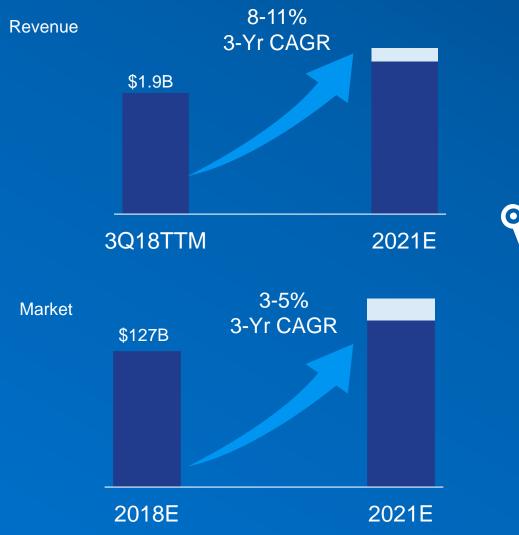


Growth drivers

- New business above market growth
 - ADAS / radar, vehicle networks, electrification
- Core business at market growth
 - Connected infotainment, powertrain, secure car access
- Value proposition
- Solution portfolio
- Innovation power
- Automotive safety & reliability



Industrial & IoT – Highly Diversified^{1,2,3,4}



Growth drivers

Processing

- 32bit microcontrollers & cross-overs
- IoT application processors
- Analog mixed-signal & connectivity

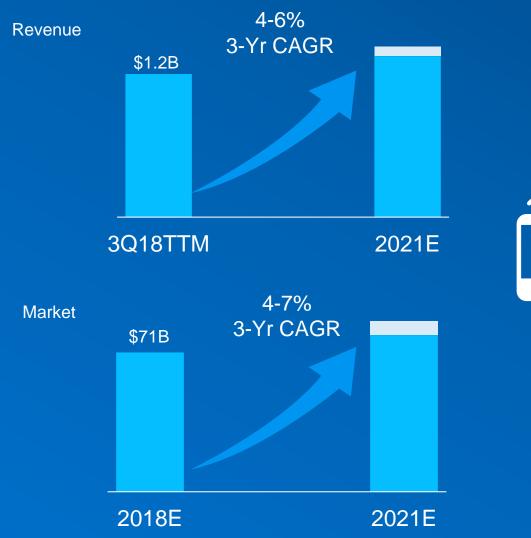
Value proposition

- Broad, scalable solutions
- Common S/W tool environment
- Deep application insights
- Channel reach
- Charts/graphics created by NXP based on Gartner research. Source: Gartner Semiconductor Forecast Database, Worldwide, 2Q18 Update (Calculations performed by NXP)
- 2. TAM-F = Semiconductor TAM excluding Memory, Optoelectronics and Discretes
- 3. Industrial/IoT includes Industrial, Consumer and Computing, excludes Ultramobile, Wearables and Smartcards

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Mobile – Specialty Supplier with High Moats^{1,2,4}



Growth drivers

- Mobile payment adoption
- New use cases (transit, access, etc.)
- High-speed mixed-signal interface

Value proposition

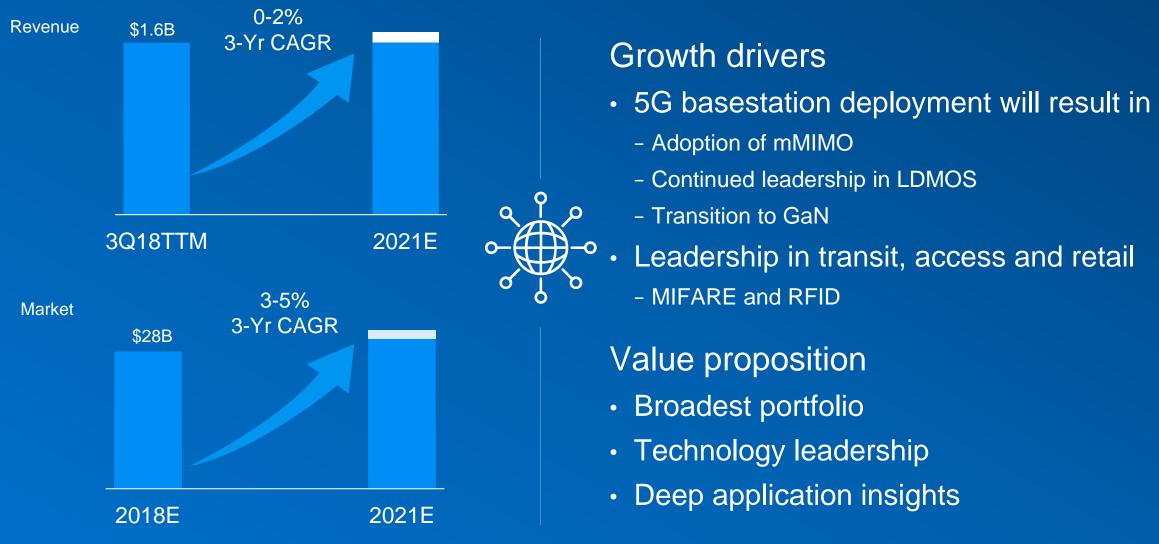
- Technology innovator and leadership
- Recognized ecosystem leader
- Deep application insights

- Charts/graphics created by NXP based on Gartner research. Source: Gartner Semiconductor Forecast Database, Worldwide, 2Q18 Update(Calculations performed by NXP)
- 2. TAM-F = Semiconductor TAM excluding Memory, Optoelectronics and Discretes
- 3. Mobile Includes Smartphones, Feature phones, Wearables and Ultramobile

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Comm. Infra. & Other – Cyclical and Project Oriented¹²



1. Charts/graphics created by NXP based on Gartner research. Source: Gartner Semiconductor Forecast Database, Worldwide, 2Q18 Update (Calculations performed by NXP) TAM-F = Semiconductor TAM excluding Memory, Optoelectronics and Discrete

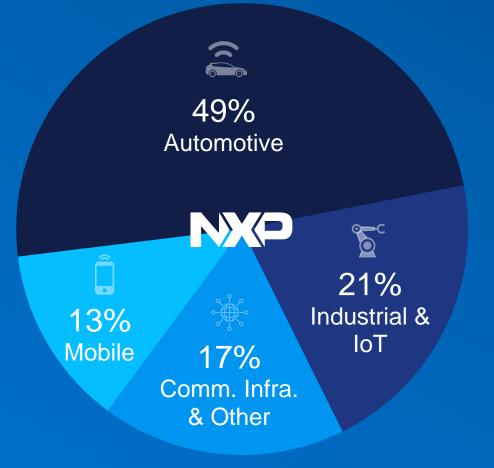
2. Comm/Infra Includes Comm/Infra and Smartcards

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Summary¹

NXP 3Q18TTM HPMS Revenue by End-market Exposure



End Market	2018E – 2021E 3-yr. CAGR
Automotive	7 – 10%
Industrial	8 – 11%
Mobile	4 – 6%
Comm. Infrastructure & Other	0 – 2%
Corporate and Others	(3%)
NXP	5-7%



Value Proposition









Driving RMS Leadership

Focused on RMS > 1.5X Multiple High Growth Markets

Profitable growth

Solutions Core Competency World-class Expertise & Team

Resolving customer pain-points

Customer focused passion to win

Maximize Shareholder Value

Strong cash flow generation



Communications Infrastructure & Others

Rick Clemmer Chief Executive Officer





RF Infrastructure Leader¹

NXP's RF Infrastructure SAM



Basestation Market

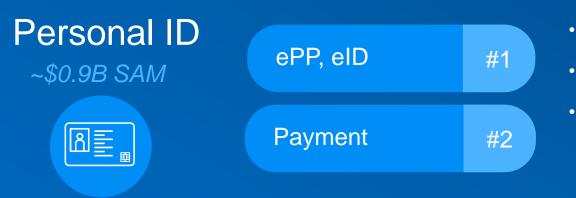
Technology & Innovation Leadership

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Market leader in RF technology and systems solutions

- Multi-year cyclical market dynamics
- Expect 3-4x content increase versus 4G build-outs
- Leader in LDMOS continued usage for <3GHz bands
 - NXP continues to deliver performance leadership
- Highly integrated mMIMO solutions deliver 8x throughput
 - Significant content increase over existing architectures
- Industry's highest linearity GaN IP, optimized for 5G
 GaN Strong customer engagements & qualification
- Highest performance SiGe mmWave solutions for 20-40Ghz
 - SiGe mmWave shipping to US wireless carriers

Regained Technology Leadership in SIS¹



- Payments on steady path since 1Q17
- Performance in line with market
- Leading technology
- 40nm Flash P71 & JCOP 4
- Unique full solution: HW / OS / Applet / MW

Smart Cities ~\$0.5B SAM





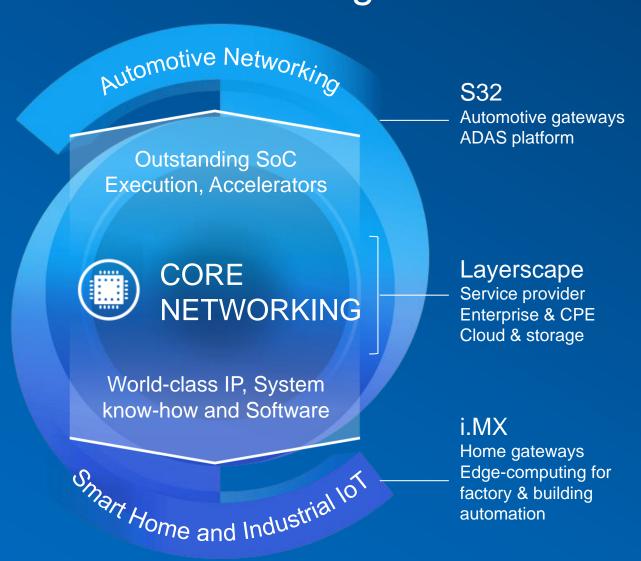


- leadership in transit & access with MIFARE[®]
 - 750+ cities world-wide & growing
- Global leader in RFID tag with UCODE, ICODE, NTAG
 - Broadest product portfolio, 20% less power consumption
 - Tag units expected to double by 2021
- Drive convergence of cards and mobile with MIFARE2GO
 - Transit solution of choice in Google Pay



Maximizing Market Impact of NXP Networking Assets

- Differentiated technology and complex SoC execution capabilities
- Continued focus on core networking markets: 5G & enterprise deployments, CPE/SMB & security, datacenter offload
- Harmonize SW platform with i.MX to accelerate IoT infrastructure opportunity
- Shared HW platform with S32
 Automotive portfolio to capture full
 potential of domain architecture



NXP Evolves its Structure to Support Profitable Growth

- Simplified organization
 - Drive execution of our stated strategy
 - Deliver platform & solutions at scale
 - -Collaborative growth
 - -Strengthened focus, speed, efficiency
- Kurt Sievers is named president
 - -Oversees all NXP business lines
 - Builds on outstanding track record of success, leading NXP to #1 position in Automotive
 - -Will lead our business to broader leadership in Secure Connections for the Smarter World







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Financial Overview

Peter Kelly Chief Financial Officer





Agenda

FINANCIAL OVERVIEW

NXP investment thesis
Our focus is operating profit
Progress since our last analyst day?
Financial model
Why invest in NXPI



NXP Investment Thesis



Market Leader in Growing Markets



Focused on Strong Profitable Growth



Shareholder Friendly



All Excess Cash Returned to Shareholders



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FINANCIAL OVERVIEW

NXP investment thesis

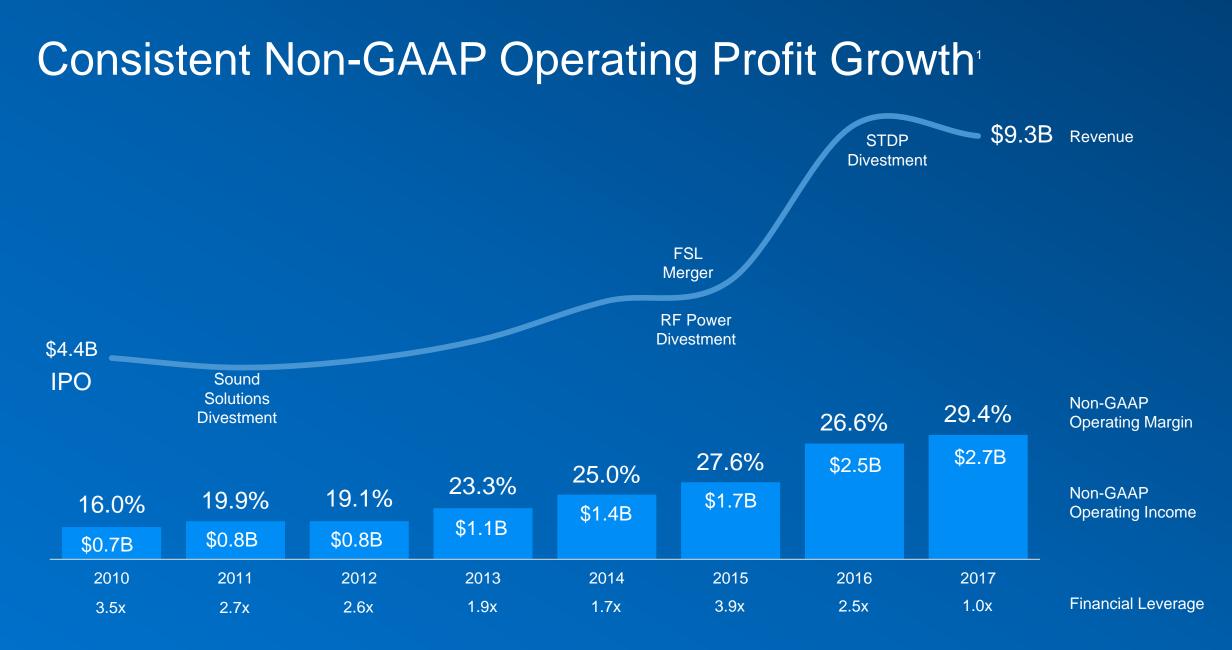
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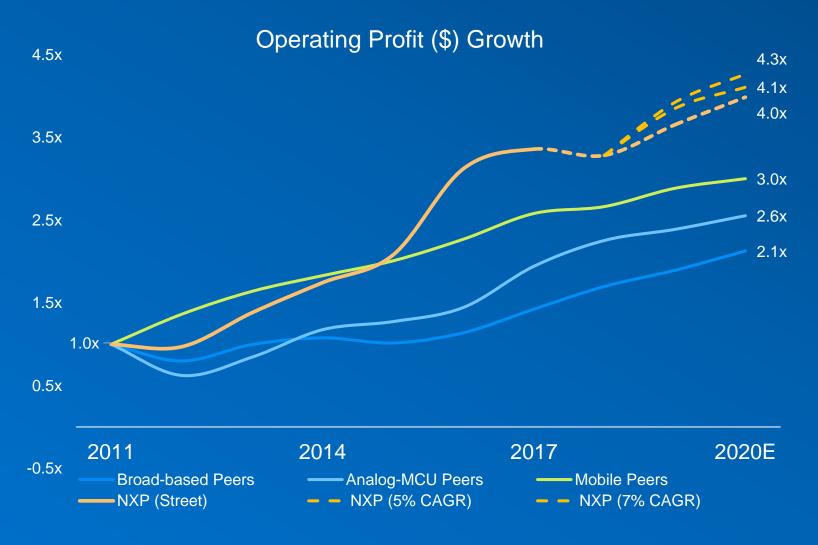




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NXP Focus is the Growth in Operating Profit¹²



NXP focus

- High RMS
- Employee engagement
- Customer satisfaction (net promoter scores)

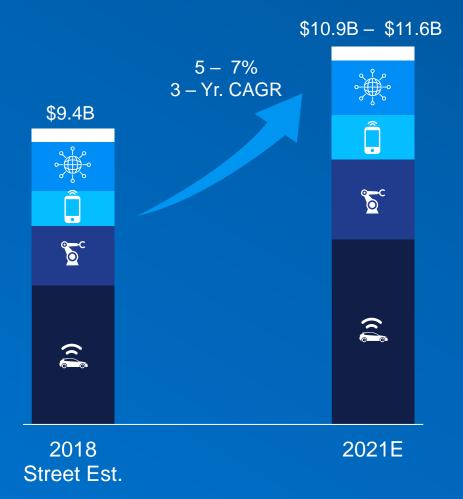
1. For Peer Groups, data reflects market capitalization weighted averaged operating profit growth; for periods 2011-2017 values are reported actuals; 2018E-2020E Wall Street sell-side estimates, including NXP, Broad-based Peers = CY, IDTI, LSCC, MPWR, ON, SLAB, XLNX; Analog-MCU Peers = ADI,IFX, MCHP,MXIM,STM,TXN; Mobile Peers = AVGO, CRUS, DLG, QCOM, QVRO, SWKS, SYNA



27 2. Source: all data sourced from FactSet

Growth Opportunity Driven by Focus End Markets¹²

Growth by End Market



End Market	Percent 3Q18TTM Revenue	2018E – 2021E 3-yr. CAGR
Automotive	47%	Up 7 to 10%
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Comm. Infra. & Other	17%	0 to up 2%
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- Total	100%	Up 5 – 7%



Drivers of Product Revenue Growth

Automotive		Growth: 7 – 10% 3–yr. CAGR • #1 Global auto semi supplier • Leadership in all focus areas	 ADAS/Radar, vehicle networks, electrification Connected infotainment, powertrain, secure car access
Industrial & IoT	Solution	Growth: 8 – 11% 3–yr. CAGR Leader in GP MCU & AP Driving analog attach to MCU 	 Broad based industrial High Performance edge & media processing Low-power edge & node processing
Mobile		Growth: 4 – 6% 3–yr. CAGR Specialty mobile supplier Leader in mobile payments Specialty analog & interface 	 Mobile wallet use-cases expansion Custom interfaces, voice & audio and charging
Comm. Infra. & Other		Growth: 0 – 2% 3–yr. CAGR Leader in secure identity-access Leader in RF power 	 mMIMO & 5G build-out to drive RF power Recognized security leadership & expertise Repurposing network processor IP & expertise



End-market to Operating Segment Map (aka Jeff's "Decoder Ring")¹



		Auto 7 – 10% CAGR	SCD 8 – 11% CAGR	SI&I 0 – 2% CAGR	SIS 0 – 2% CAGR
SCD Auto	Automotive 7 – 10% CAGR	• Entire Auto	 Infotainment AP 		
SCD	Industrial & IoT 8 – 11% CAGR		 Industrial & IoT MCU Industrial & IoT AP Low power connectivity NFC readers 	High perf. analogAC-DC powerSpecialty ASSPs	
SII SCD	Mobile 4 – 6% CAGR		 Mobile wallet 	 Custom interfaces Power management Voice & audio 	
SIS SII	Comm. Infra. & Other 0 – 2% CAGR			Specialty RFDigital networking	Entire SIS
		Auto	Auto Ind & IoT	Ind & IoT Mobile Comm & Infra	Comm & Infra
30 1 3018 TTM financial data	based on 4017-3018E (mid-point quide)	Business Lines			

Agenda FINANCIAL OVERVIEW NXP investment thesis Our focus is operating profit Progress since our last analyst day?



Performance Versus the NXP Analyst Day 2016^{1,2,3}

Business Lines (% '17 Revenue)	Analyst Day 2016	2017 Y-Y	3Q18TTM Y-Y	Comment vs. Expectations at Analyst Day 2016
Auto (41%)	Up 6 to 9%	11%	9%	Performance at high-end of range
SCD (30%)	Up 10 to 15%	21%	14%	Momentum above plan
SI&I (21%)	Up 5 to 9%	3%	(5%)	Legacy DN products decline
SIS (6%)	Up 2 to 5%	(29%)	3%	Bank-card market saturation
Total NXP Revenue Growth	5 – 7%	10%	7%	
Non-GAAP Gross Margin	53 – 57%	53.4%	53.3%	Mix and input costs
Non-GAAP R&D %	14 – 16%	15.7%	16.7%	Investing for future growth
Non-GAAP SG&A %	6 – 8%	8.3%	8.0%	
Non-GAAP Operating Margin	31 – 34%	29.5%	28.6%	

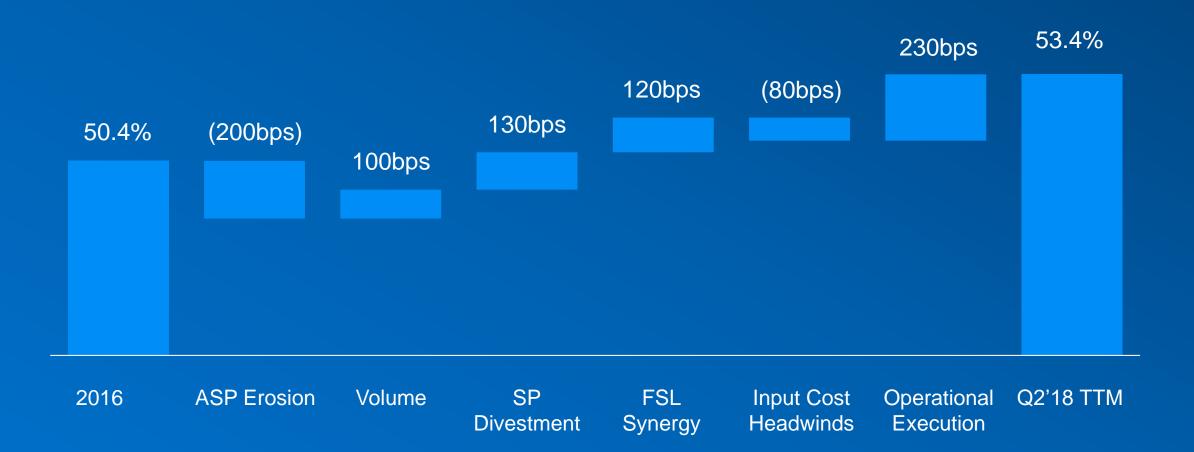
1. Reconciliations of non-GAAP measures throughout this presentation to the most comparable measures calculated in accordance with GAAP can be found in the "NXP Historic Financial Model" file in the Financial Information page of the NXP Investor Relations section of our website at www.nxp.com/investor.

2. 2017 Y-Y and 3Q18TTM Y-Y, excludes Standard Products

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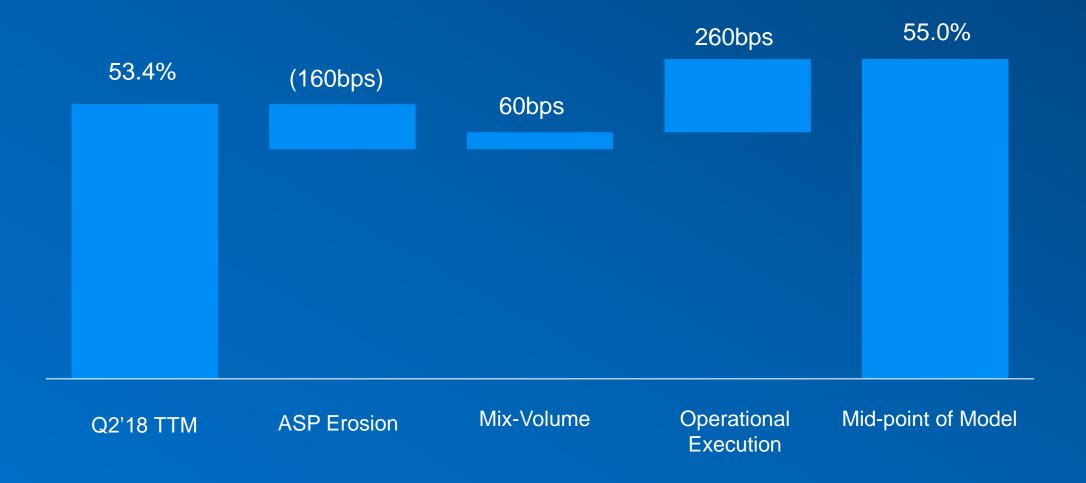
3. 3Q18 TTM financial data based on 4Q17-3Q18E (mid-point guide).

Track Record of Non-GAAP Gross Margin Expansion¹





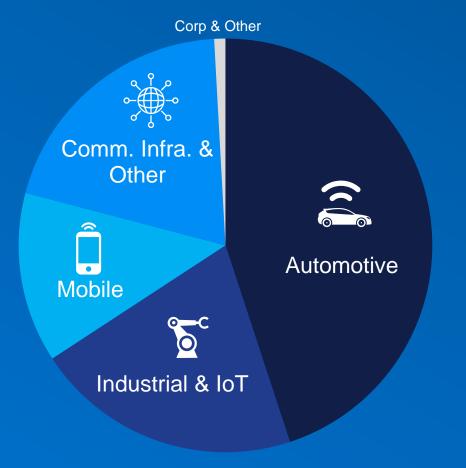
Path to Mid-Point of Model Non-GAAP Gross Margin Exiting 2019





Focused R&D Investments to Drive Future Growth¹²

Non-GAAP R&D Investment



Major R&D Investments

- Automotive: up 15% CAGR
 - Processing & Networking: S32, auto gateway, i.MX-auto, Ethernet
 - ADAS: radar, vision, V2X
 - Power: power management, battery management systems
- Industrial: up 15% CAGR
 - Processing: i.MX Hi-perf edge, i.MX RT Ultra-low power, GP MCU
- Mobile: 3% CAGR
 - Security: eSE, RF, new applications
 - High-speed interfaces
 - Wireless charging
- Comm. Infra. & Other: down 6% CAGR
 - RF: GaN & LDMOS Pwr Amp., mmWave, mMIMO, new applications
 - Networking: 64-bit Layerscape
 - Consumer security solutions



2. 2016 – 2018E CAGR

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Financial Model

	2018E – 2021E
Focused Market Growth ⁽¹⁾	3 - 5%
NXP Growth ⁽¹⁾	5 - 7%
Non-GAAP Gross Margin	53 - 57%
Non-GAAP R&D	14 - 16%
Non-GAAP SG&A	6 - 8%
Non-GAAP Operating Margin	31 - 34%
Non-GAAP Operating Income Growth	~8 - 14%



Modeling Housekeeping Issues¹

	2019E	2020E	2021E
Non-GAAP Cash Taxes	8%	11%	12%
Incidental Taxes	\$166M	\$26M	-
Stock Based Compensation	\$365M	\$365M	\$350M
Non-Controlling Interest	\$50M	\$45M	\$45M



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Shareholder Friendly



Strong focus on cash management, and who the cash belongs to



Strong financial alignment of management and shareholders



Experienced management team who are committed to the company and focused on driving value for shareholders

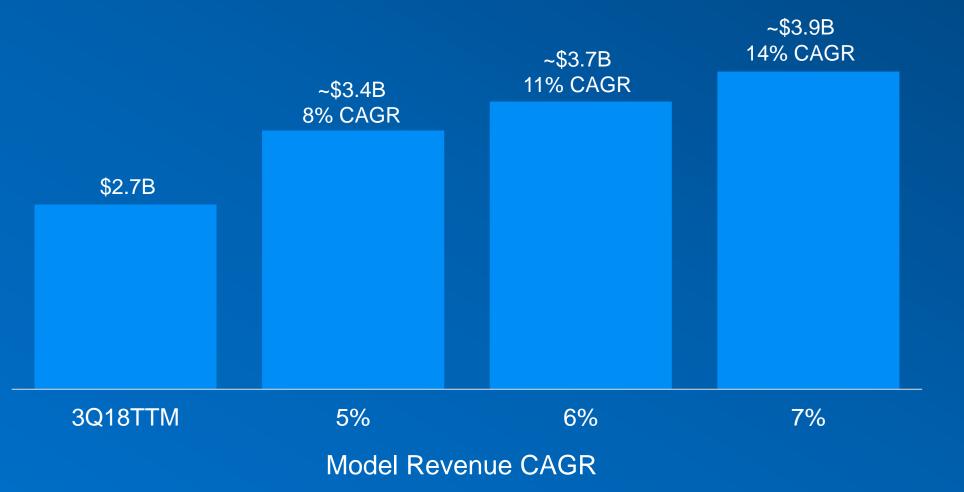


Always ready to listen to our shareholders



Illustrative Sensitivities to Revenue Growth¹

Estimated Non-GAAP Operating Income (\$B) in 2021



1. Reconciliations of non-GAAP measures throughout this presentation to the most comparable measures calculated in accordance with GAAP can be found in the "NXP Historic Financial Model" file in the Financial Information page of the NXP Investor Relations section of our website at www.nxp.com/investor.

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2019 – 2021 We Will Generate Significant Non-GAAP FCF¹²

Capital Generation

- Potential to generate \$7B \$8B of cumulative non-GAAP free cash flow
- Business supports additional debt capacity of up to 2x adding \$2B \$4B of cash
- Results in \$9B \$12B to invest in the business and/or return to our owners

Capital Return Options

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- Dividends: Target payout ratio of 20% to 25% of CFO
- Buybacks: We have the capacity to continue to do substantial buybacks
 - NXP will still be subject to a deemed dividend on buy backs in 2019

Strong Business Model, Balance Sheet, and Cash Flow! Significant opportunity to create shareholder value!





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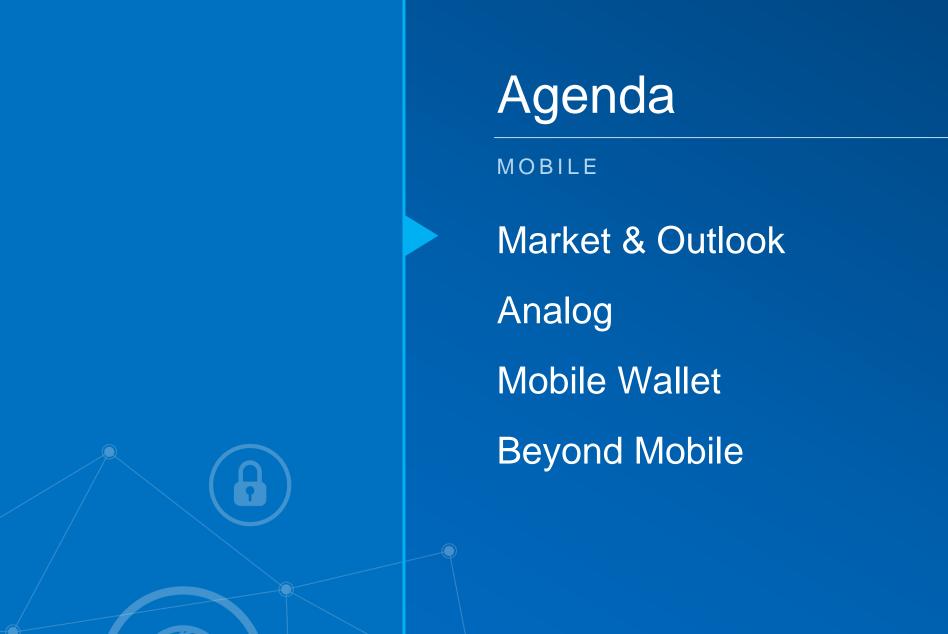
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Mobile

Rafael Sotomayor Senior VP & General Manager









\$1.2B Mobile Business Expected to Grow 4-6%¹²

Phone Volume

0 - 1% 3-Yr CAGR

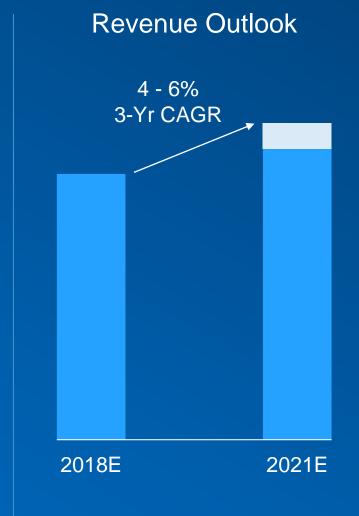


Revenue & Growth Drivers





Secure Mobile Wallet eSE/NFC attach-rate increase through use-cases expansions





Selectively Leveraging Our Analog Portfolio in Mobile¹

Interfaces

High Performance Custom ICs

Custom high-performance interfaces

Connector and cable interfaces Switches, authentication, protection...

Multi-generation stickiness In-depth system knowledge

> >6B Interface ICs shipped



Voice and Audio

Smart Haptic & Stereo Amp Leader in Voice Enhancement

Voice, audio & haptic solutions Smart amp, haptic driver, algorithms

Hi-Fi audio with speaker protection Highest dynamic range, bass sounds

Best voice calling experience Noise, echo, wind suppression



Smart amps shipped

>3B

Phones with NXP voice software



Charging

Certified QC4.0 Charging Fast Charging with Type-C PD

End-to-end USB-C, PD3.0 Direct charger, AC-DC, OVP,...

2X faster, 2X cooler charging 2:1 direct charging

SAM CAGR 40%



Mobile Wallet Growth Driven Enabling OEMs and Services 2014 ONE OEM, **ONE USE CASE** Applets Secure OS Service Providers NFC Service by OEM eSE OEM Mobile Payment Mobile Wallet



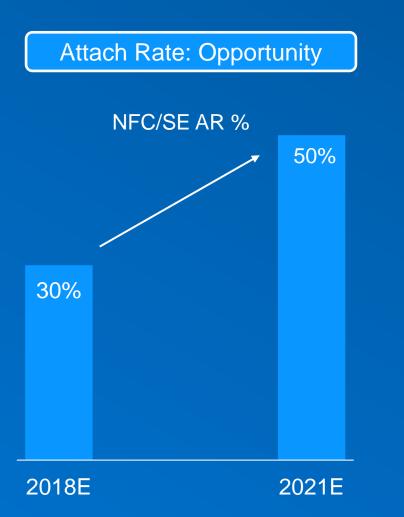
Growth Driven Enabling OEMs and Services





Mobile Wallet Use-Cases Expansion Drives Growth¹

Expanding Use-cases







Continued leadership in mobile payment From high-end smart phone to feature phones & wearables



Driving mobile transit From China to other regions

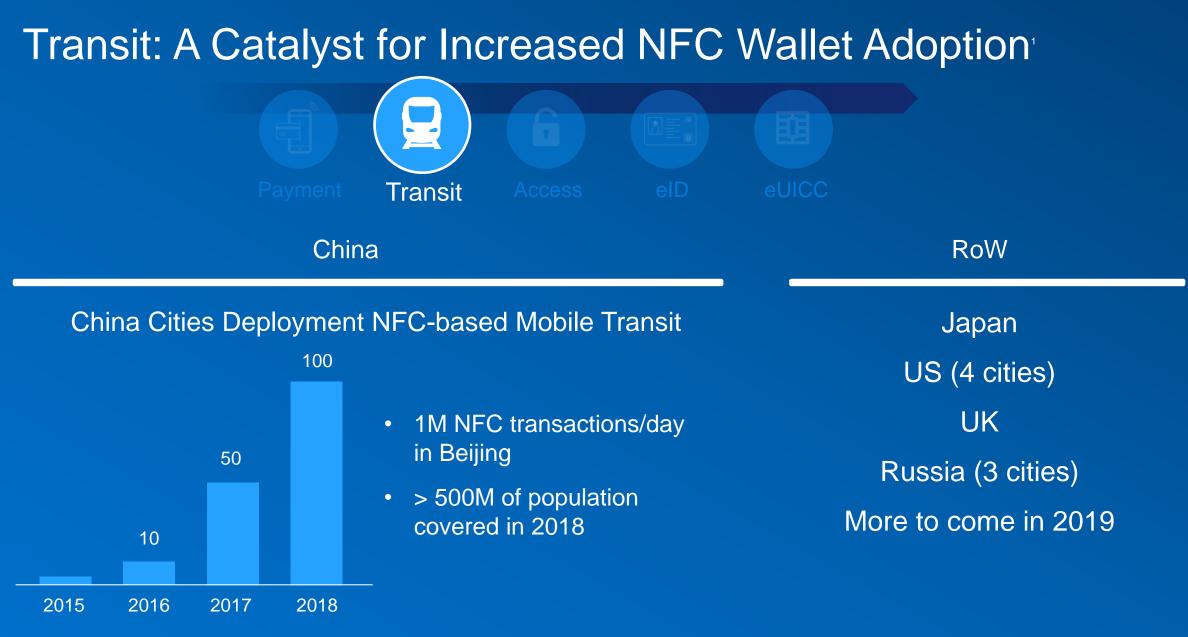


Deploying mobile access use-cases Car, building, university access...





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Reliance Jio Phone

Partnered with NXP to drive innovative secure services in India



- Driving secure mobile payment to the masses
- JioPhone and JioPhone2: Two feature phones enabled with secure services



- Secure services
 - Closed loop P2P payment
 - UPI payment initiative
 - Mobile point of sale (mPOS) support
 - Mobile transit services throughout India



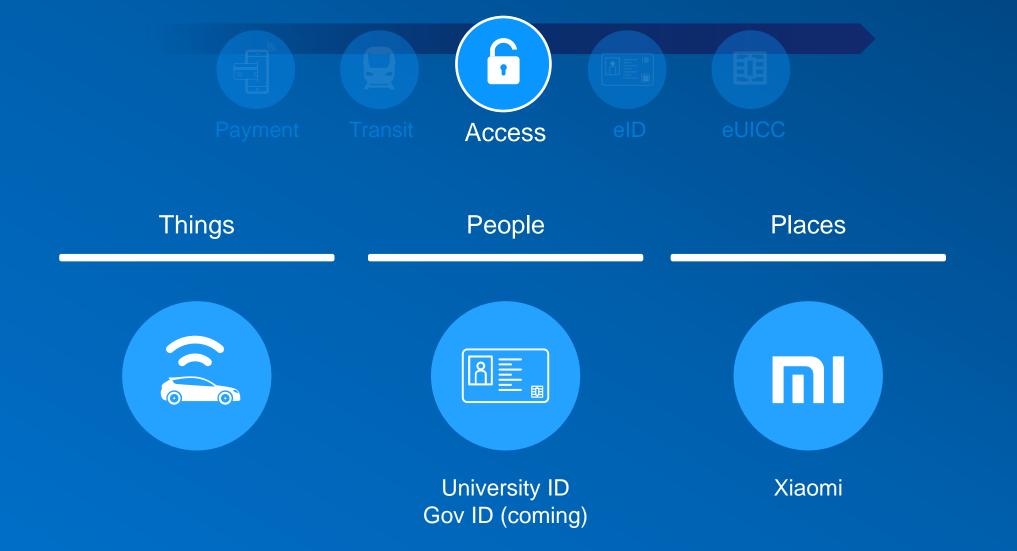
NXP Provides

- Hardware components: SE/NFC
- Secure OS and Applications
- Service Enablement





The Next Wave of Use Cases





Expanding Security Platform to IoT



Services



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Industrial & IoT

Geoff Lees Senior VP & General Manager





Agenda

INDUSTRIAL & IOT

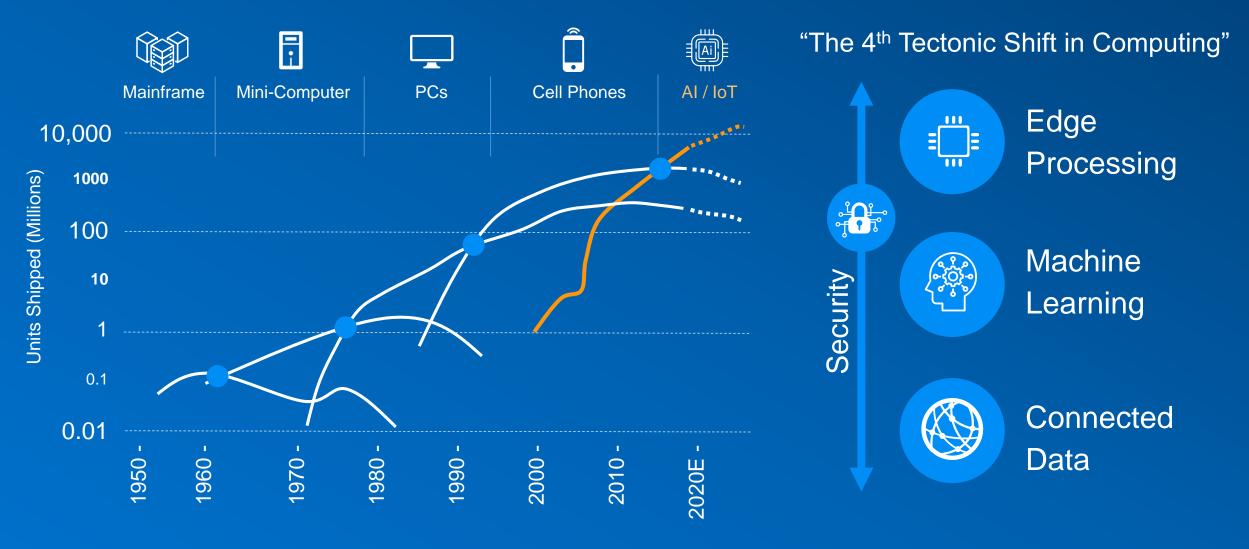
The AI / IoT Disruption & NXP Growth Opportunity Understanding Customer Pain Points NXP Solutions:

- Unique Processing Continuum
- Simplifying Software & Systems Complexity

Summary



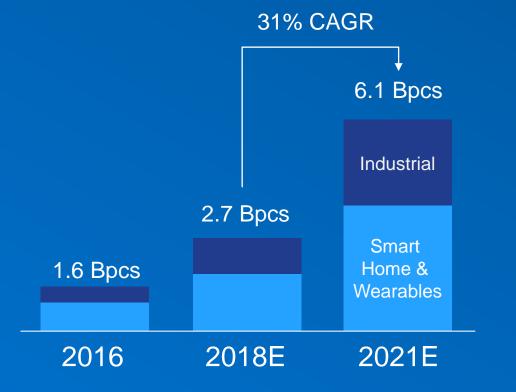
The AI / IoT Era Will Create New Industry Leaders¹







IoT Endpoints, Worldwide



... Changing the Rules of Engagement with the Market





Very diverse end devices Fragmented customer base Wide range of applications & ecosystem

1. Charts/graphics created by NXP based on Gartner research. Source: Gartner Forecast: Internet of Things — Endpoints and Associated Services, Worldwide, 2017 (Calculations performed by NXP)

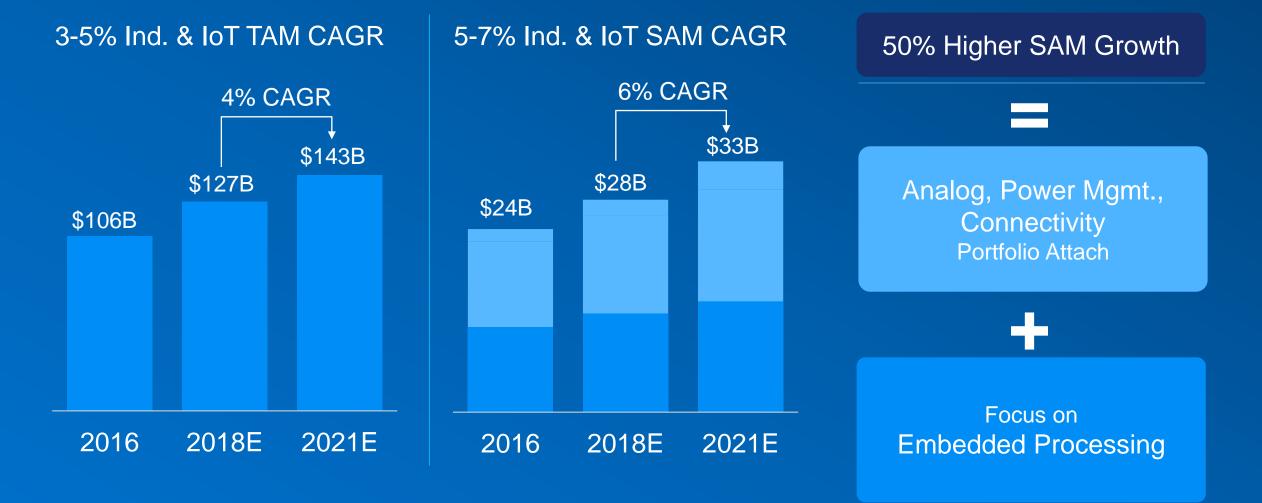
2. Excludes Automotive

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publication date (and not as of the date of this Investor Presentation) and the opinions expressed in the Gartner Report(s) are subject to change without notice



NXP Industrial & IoT SAM Outgrowing Focused TAM¹²



1. Charts/graphics created by NXP based on Gartner research. Source: Gartner Semiconductor Forecast Database, Worldwide, 2Q18 Update*, ** (Calculations performed by NXP)

- 2. TAM-F = Semiconductor TAM excluding Memory, Opto, Discretes
- 3. Industrial/IoT includes Industrial, Consumer and Computing, excludes Ultramobile, Wearables and Smartcards

4. The Gartner Report(s) described herein, (the "Gartner Report(s)") represent(s) research opinion or viewpoints published, as part of a syndicated subscription service, by Gartner, Inc. ("Gartner"), and are not representations of fact. Each Gartner Report speaks as of its original publication date (and not as of the date of this Investor Presentation) and the opinions expressed in the Gartner Report(s) are subject to change without notice



NXP Industrial & IoT Applications



Industrial Control & PLCs



Industrial Drive & Robotics



Smart Energy



Appliances



Smart Home and Building Control



Handheld Scanners, Printers, POS



Medical



PC Peripheral & Gaming



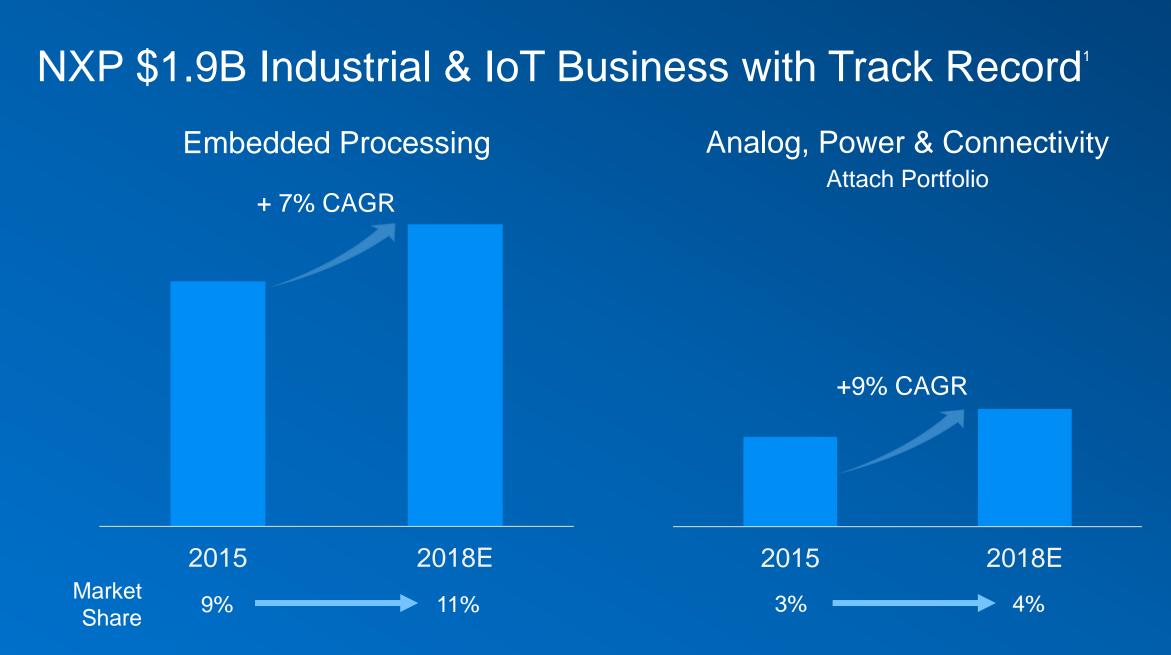
High End Audio



Customer Products

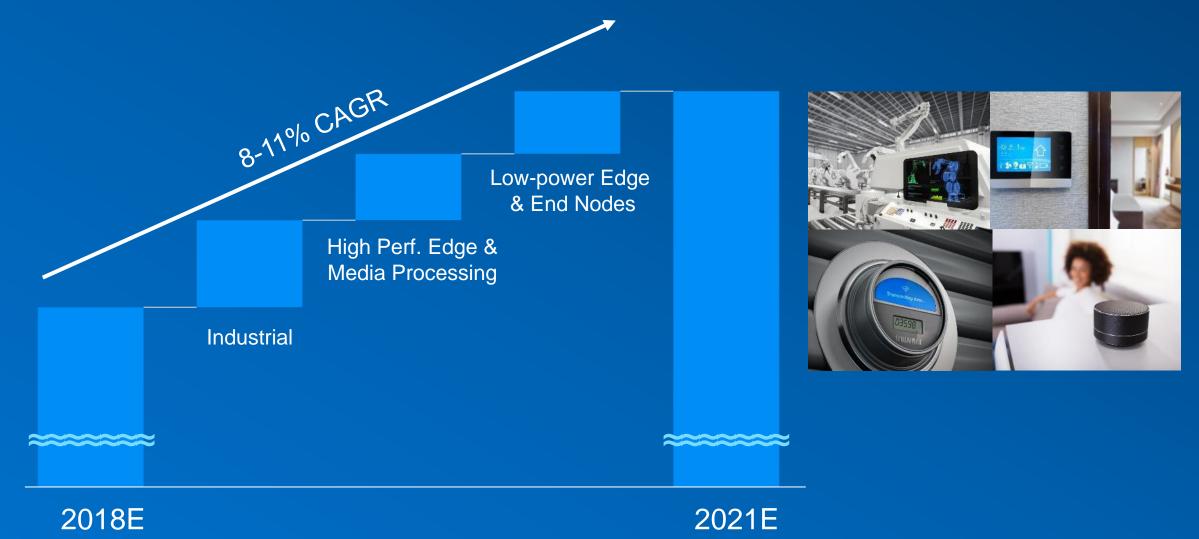








Accelerating Industrial & IoT Revenue Growth





Agenda

INDUSTRIAL & IOT

The AI / IoT Disruption & NXP Growth Opportunity

Understanding Customer Pain Points

NXP Solutions:

- Unique Processing Continuum
- Simplifying Software & Systems Complexity

Summary



Customer Pain-Point: Rising Cost of IoT Solutions¹





Customer Pain-points: System Complexity & Security



Very High System Complexity

"70% of embedded developers decide on the processor's ecosystem first"

> 2017 Embedded Developers Survey

EETimes Embedded

Diverse cloud & Al solutions



Fragmented connectivity protocols

🛞 Bluetooth" ์ d'HREAD Wi Fi ZiqBee WAVE sigfox LoRa

Operating system & software portability

Zephyr Linux





Data Privacy & **Security Concerns**

Data Breach Examples

Retail / Healthcare Jun 2018, Feb 2015, May 2014, Sep 2014, Dec 2013

Social Media / Search June 2016, Aug 2013

Banking / Credit Rating July 2017, June 2014

Airlines Sep 2018

Government regulations

GDPR ≴







Agenda

INDUSTRIAL & IOT

The AI / IoT Disruption & NXP Growth Opportunity Understanding Customer Pain Points

NXP Solutions:

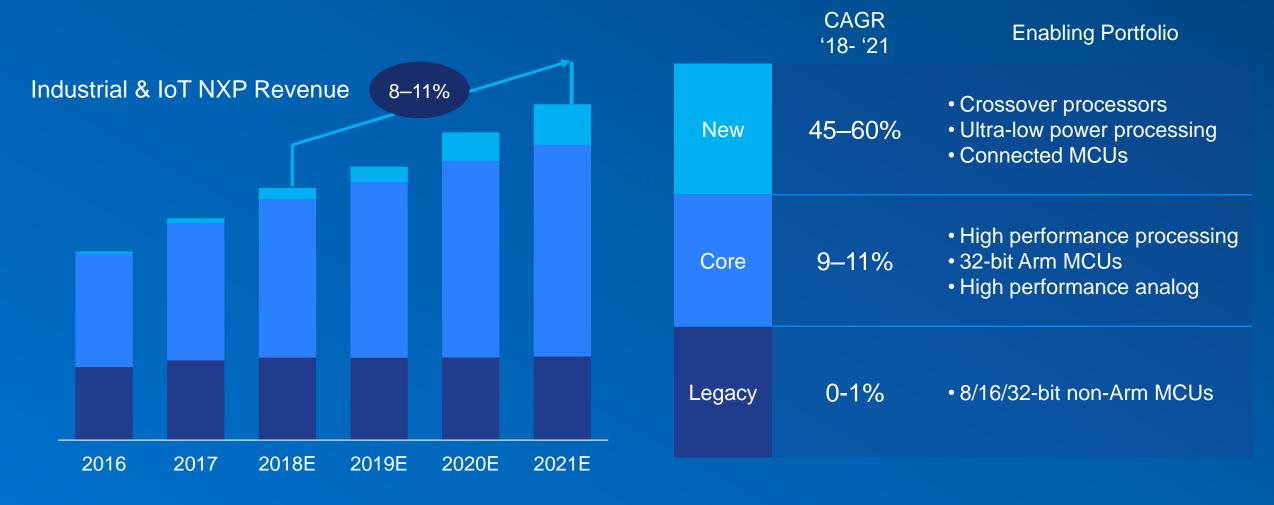
- Unique Processing Continuum
- Simplifying Software & Systems Complexity

Summary



Consistent Broad Based Growth

Accelerated by high impact growth portfolio





Industrial & IoT Processing Requirements¹

End nodes

Edge processing

Industrial & Home Control

Single core, low-power, cost-sensitive

Multi-core, high-performance

Limited storage, short range communication Local data management & decision making, wide Area & cloud connectivity

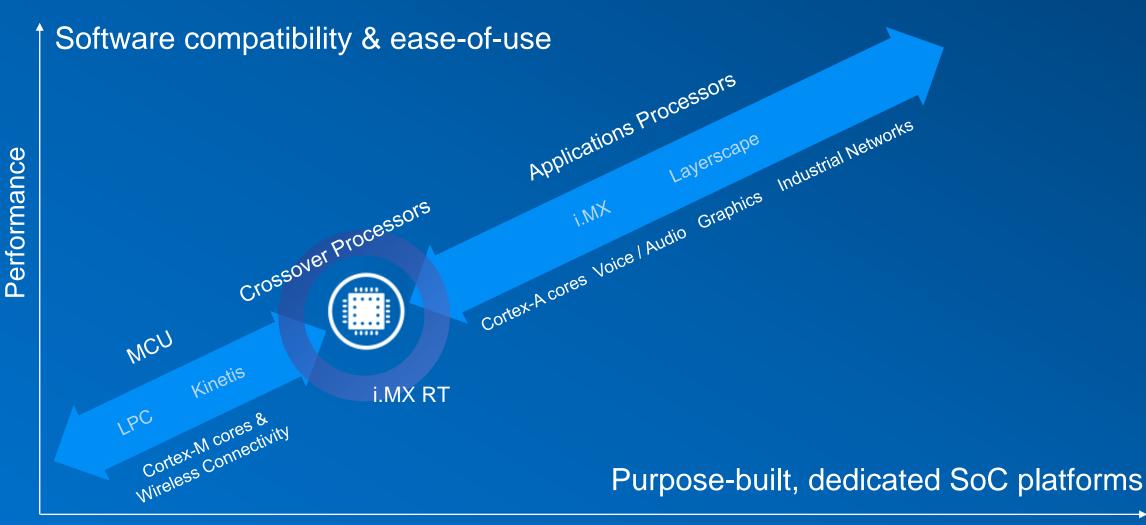
Embedded security

+ Logical & Network security

Microcontrollers (MCUs) Applications Processors (APs)

~\$13B Embedded Processing SAM

NXP Scalable Industrial & IoT Processing Continuum



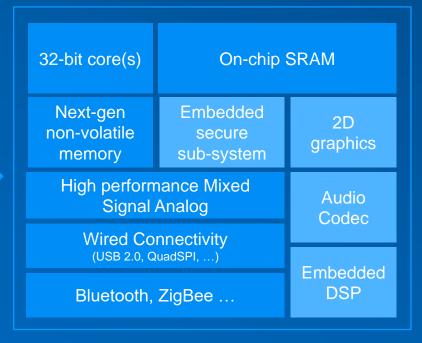
Functional Integration



Dramatic Increase in Complexity of Embedded Processing

i.MX RT

MCU8/16/32-
bit coreOn-chip
SRAMWired
Connectivity
(USB 1.0/2.0,
UART, SDIO)Embedded flashMixed
signal
analog



i.MX

64-bit cores	On-chip SRAM	3D + 2D graphics
32-bit cores	Embedded secure sub-system	4K HDR Display
Machine	Mixed Signal	Audio / Video Codec
learningAnalogHigh-speed connectivity (USB 3.0, TSN, QuadSPI,)		Embedded DSP

"Not your father's MCU anymore"

- Millions of transistors
- Older technology nodes
- Bulk silicon

- Billions of transistors
- 40nm & below technology nodes
- High-K Metal Gate, FD-SOI, FinFET



Crossover Processing Market Opportunity^{1,23}



74

2. Definition: Embedded Processing = Applications Processors (AP) + MCU

3. Embedded processing SAM excludes Automotive, Comms. Infrastructure & Smartcard



Winning the Industrial Embedding Processing Challenge

Revenue Growth

100%

Low-power Edge & End Nodes

High Perf. Edge & Media

Industrial

Expected 2018 – 2021 Revenue Growth Drivers Key Applications



Industrial Gateways

ூ

0-¢

₩₩ ▼ Human-Machine Interface

Machine Vision

Robotics

Industrial

Scanners



<u>م</u>لم ۲

> Wired Connectivity

Key Capabilities

Scalability

Software

Security

with Common

Key Portfolio Solutions

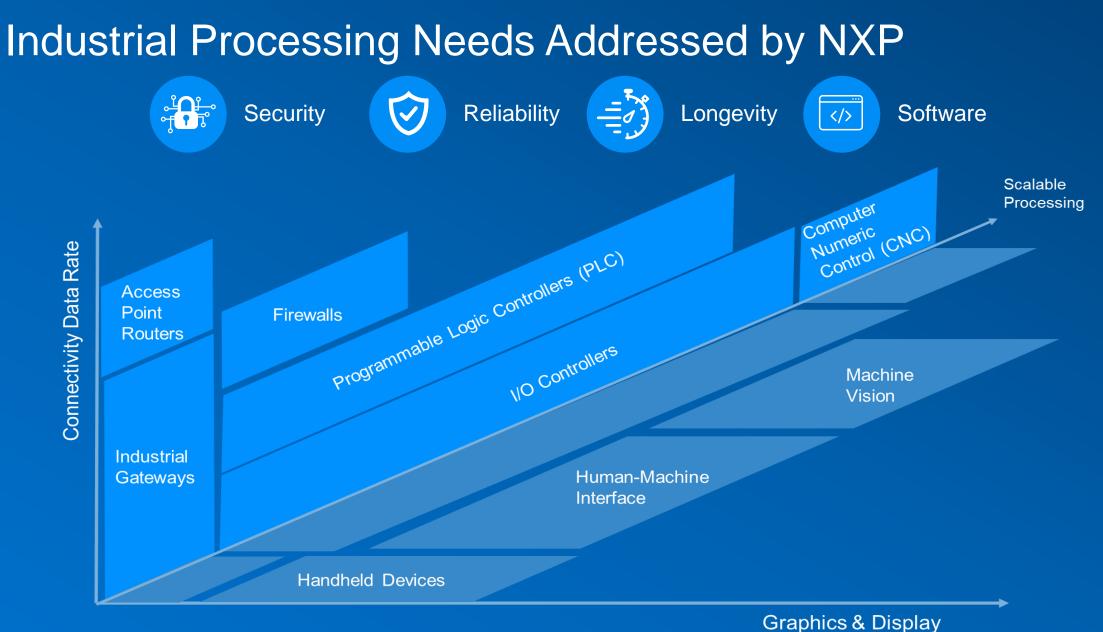
i.MX 6, 7, 8, 8M High performance, 3D graphics

Layerscape High-speed Ethernet, TSN

i.MX RT Highest performing MCUs in the market

Kinetis & LPC Low cost to high integration









Graphics & Display

Growing in the High Performance Edge & Media Processing

Revenue Growth

100%

Low-power Edge & End Nodes

High Perf. Edge & Media

Expected 2018 - 2021**Revenue Growth Drivers** **Key Applications**



Smart Home

Video Surveillance



Video OTT



Key Capabilities



Video Codec

i.MX 8 & 8M High perf., 4K HDR, 3D Graphics

Key Portfolio Solutions



i.MX 7

Balanced Power - Performance



i.MX RT Crossover Highest performing MCUs in the market

Kinetis & LPC High performance & Analog Mixed Signal



Enabling Audio & Voice Processing at the Edge¹ "Voice control front end to grow at 29% CAGR ('17-'22) in the Smart Home"

Voice

Speech

Music



Low-cost addition of voice recognition (e.g. Alexa voice services) for end nodes Wake-word, natural language processing & ML applications on integrated DSP Dolby ATMOS & DTS X: advanced codecs for high-fidelity streaming on Cortex-A

Low-power i.MX, MCUs

Performance i.MX, RT Crossover

High Performance i.MX

One unified audio software framework to meet any customer need



Enabling Audio & Voice Processing at the Edge ¹²³ "Voice control front end to grow at 29% CAGR ('17-'22) in the Smart Home"

NXP Enabled Smart Speakers



Google Voice Assist





Alexa Voice Services

amazon al<u>exa</u>





NXP i.MX7D 2-Mic Dev Kit for Amazon AVS

Voice Solutions for China





NXP i.MX8M Largest Voice Solution provider for Mandarin



2. Amazon AVS developer website

80



Growing in Low-Power Edge & End Node Processing

Revenue Growth

100%

Low-power Edge & End Nodes

High Perf. Edge & Media

Expected 2018 - 2021**Revenue Growth Drivers** **Key Applications**



HÂH

Connected Me

Smart Retail



Smart Buildings



(())) ()))

4

Voice Control

Key Capabilities

Ultra-low

Wireless

Connectivity

Power

Key Portfolio Solutions

i.MX 6 High performance, 3D graphics

i.MX 7ULP Industry's best ultra-low power

i.MX RT Highest performing MCU & DSP platform

Kinetis & LPC Low cost to high integration

Connected MCUs Multi-protocol (BLE, Zigbee, Thread)



Leading Low-Power Edge & End Node Solutions

Bringing Cloud to the End Node with Low-cost MCUs



Low-cost Voice Enablement with i.MX RT

NXP BoM • i.MX RT1050 MCU

- Analog Amplifier
- Authentication Secure Element

Ultra-low power wearables with Low-power i.MX

- Industry's best power efficiency (15uW in deep sleep mode)
- Low power GPUs for wearables and IoT
- Industry's 1st Embedded Processor based on FD-SOI Technology



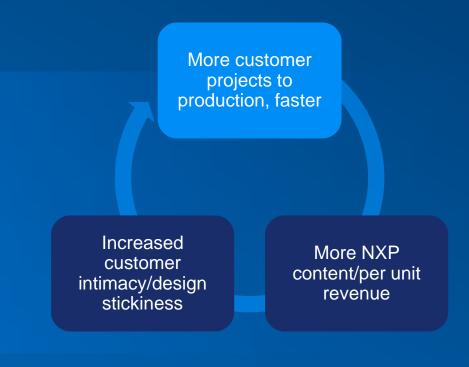


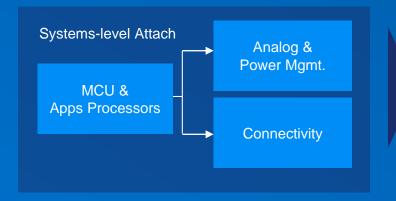
NXP Solutions for Industrial & IoT

Lead with the Processor Basis for all intelligent systems

Bring the Software Glue that holds the system together, delivers pricing power

Attach Peripheral Devices Pull through incremental NXP content







IoT Prototyping Kit IoT Modules



IoT Edge Compute Gateway



Wireless Power

Voice Solutions









Agenda

INDUSTRIAL & IOT

The AI / IoT Disruption & NXP Growth Opportunity Understanding Customer Pain Points

NXP Solutions:

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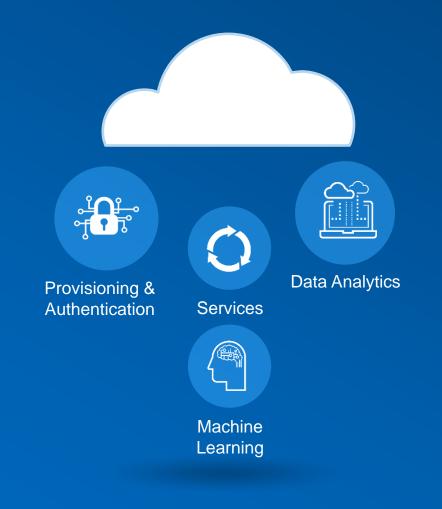
Summary



Network Edge



Cloud Infrastructure





Processing + Software 'Glue' Connects Network Edge to the Cloud





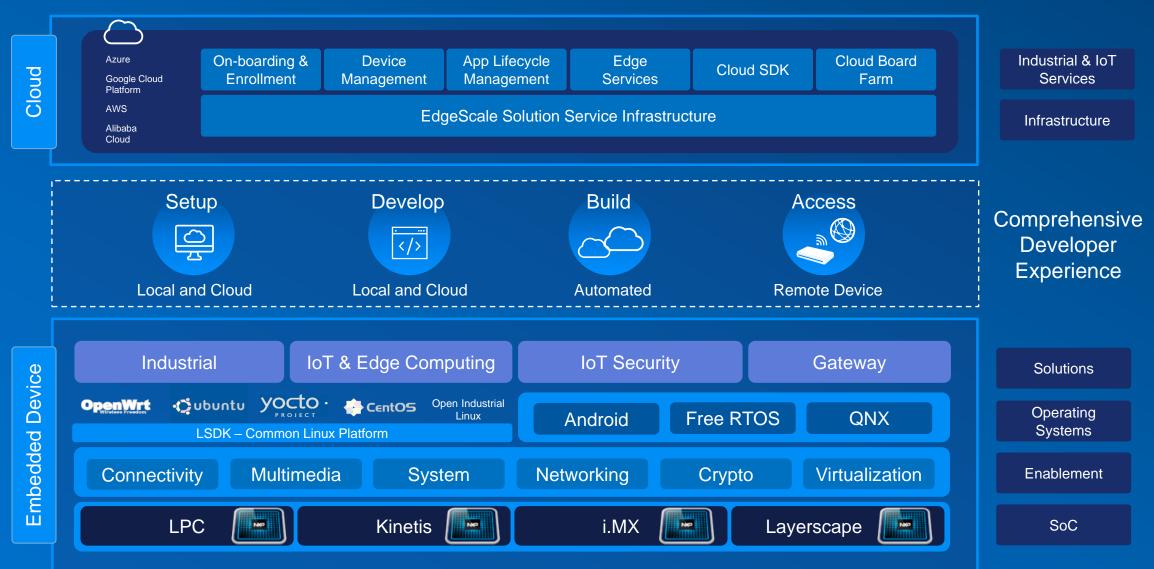
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The Future of Developer Experience





End-to-End Security in an Insecure World Scalable security for different threat profiles





NXP Local Area Connectivity Solutions Leadership



) Ultra-low power BLE for Hearables

Single-protocol MCUs (BLE-only or Zigbee/Thread – only)

) Multi-protocol MCUs (BLE + Zigbee/Thread)

2018 Industry Leading Wireless MCU launch

- Dual-core, multi-protocol connectivity with leading edge security
- Highest on-chip memory for expanded secure mesh networks
- All in a single chip



Wide Area Connectivity Solutions



Current Focus with 2018 – 2021 Revenue Impact

Turn-key Solutions NXP + Wi-Fi module/boards



'IoT-on-a-Chip' i.MX + Wi-Fi/BT



Modular design
Scalable to customer need

Future Solution

Integrated Wi-Fi chipset

- Internally developed 802.11ac/ax for top-tier enterprise customer
- Industrial & IoT 802.11ac + BLE scaled down solution in development
 - Sampling at end of 2019



Pre-certified for faster time-to-market

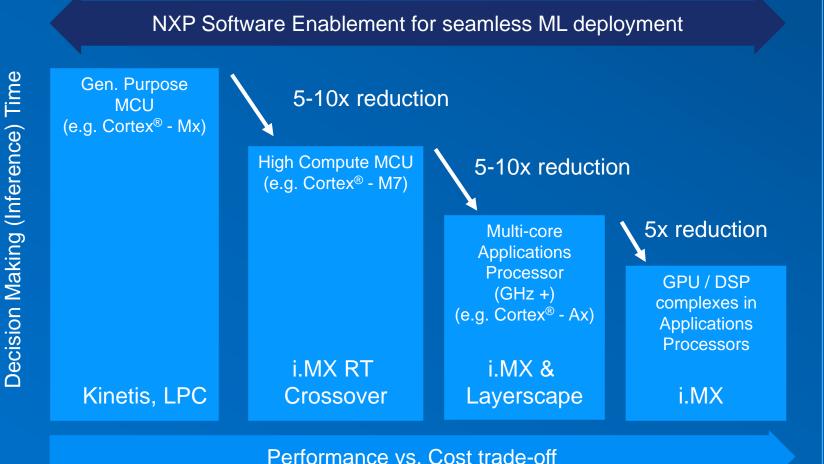
NXP Enabling Machine Learning Revolution



Scalable & optimized inference engines across Embedded Processing continuum



Edge Compute Enabler – Scalable Inference Balancing cost vs. end-user experience



Partnering with Google to bring ML Accelerator (TPU) to the edge

NXP i.MX Google TPU **Apps Processor**



Bringing intelligence to the edge with Cloud IoT Introducing the Edge TPU **Development Kit**



Industrial & IoT – NXP Value Proposition

Industrial Automation





- Open Industrial Linux (OpenIL)
- OT and IT convergence solution
- TSN scheduling service
- Zero-touch provisioning and replacement
- Zero down-time operation

- Edge AI / ML solutions
- Edge computing orchestration
- End-to-end dataflow construction and customization
- Digital device "shadow"
- Virtual function aggregation and virtual device management







- Secure manufacturing
- Secure device on-boarding and provisioning
- Secure enrollment and re-enrollment
- Cloud integration
- Independent secure identity
 management



Agenda

INDUSTRIAL & IOT

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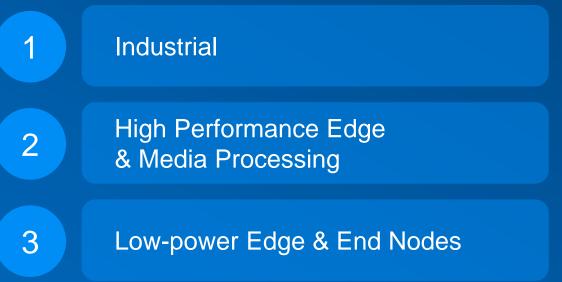


Industrial & IoT Growth Expectations Summary¹²

2018 - 2021 3-Year CAGR

NXP Industrial & IoT Revenues	8-11%
Industrial & IoT SAM	5-7%
Industrial & IoT TAM	3-5%

Broad-based growth + select high impact growth drivers





Uniquely Positioned for Industrial & IoT Edge Compute





INVESTOR DAY 2018

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Automotive

Kurt Sievers President





Agenda

AUTOMOTIVE - SAFE, SECURE MOBILITY

Megatrends

Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

- ADAS → Autonomy
- Connected Infotainment
- Network Infrastructure
- Electrification

Summary



Megatrends Transform Automotive Industry

Connected Infotainment

 $ADAS \rightarrow Autonomy$

Electrification







ZERO Time Wasted **ZERO** Accidents/Congestion ZERO Emissions

Safe and Secure Mobility



Megatrends Sustainably Boost Semi Car Content¹²

Connected Infotainment

ADAS \rightarrow Autonomy

Electrification







+\$100 Premium Experience +\$150 Level 2 +\$600 Level 3 +\$1200 Level 4&5 +\$400 Hybrid +\$450 Full Electric

Safe and Secure Mobility

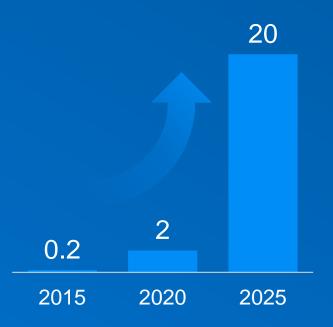
... from \$380 average semi value (TAM) per car in 2018



Megatrends Drive Exponential Performance Requirement[®]

Compute Performance

Data Generation (TeraByte per hour)

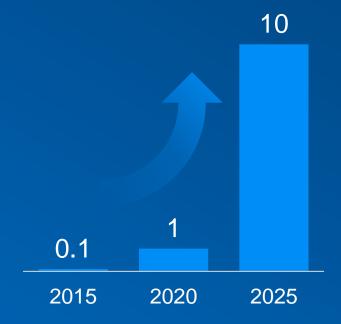


- Dramatically more sensors
- Higher precision



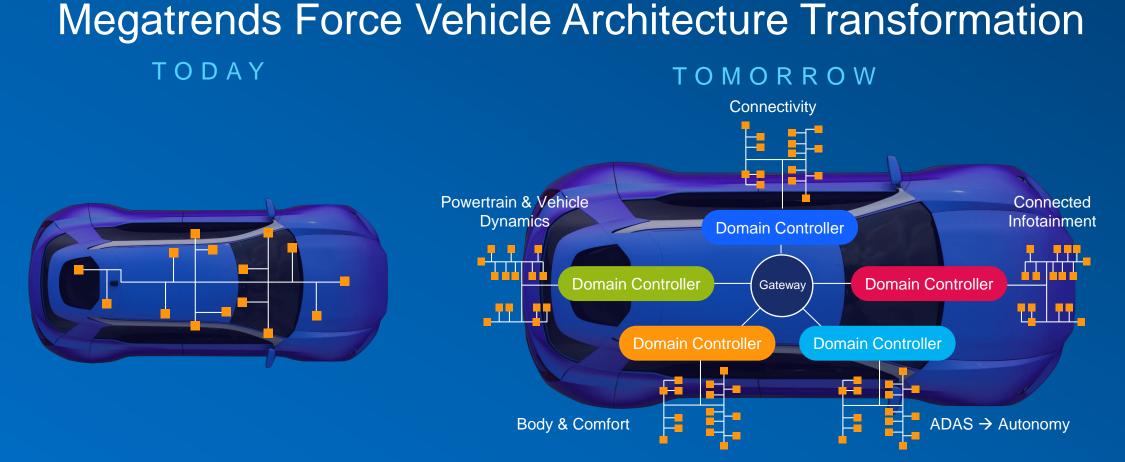
- ADAS & autonomy
- e-Cockpit





- Loads of data (on & off board)
- Real-time distributed applications





Distributed Flat Architecture

- Low bandwidth network
- One MCU per application

Domain Architecture

- High performance domain MPUs
- Edge nodes & sensors
- High bandwidth
- Gateway
- Safety & security



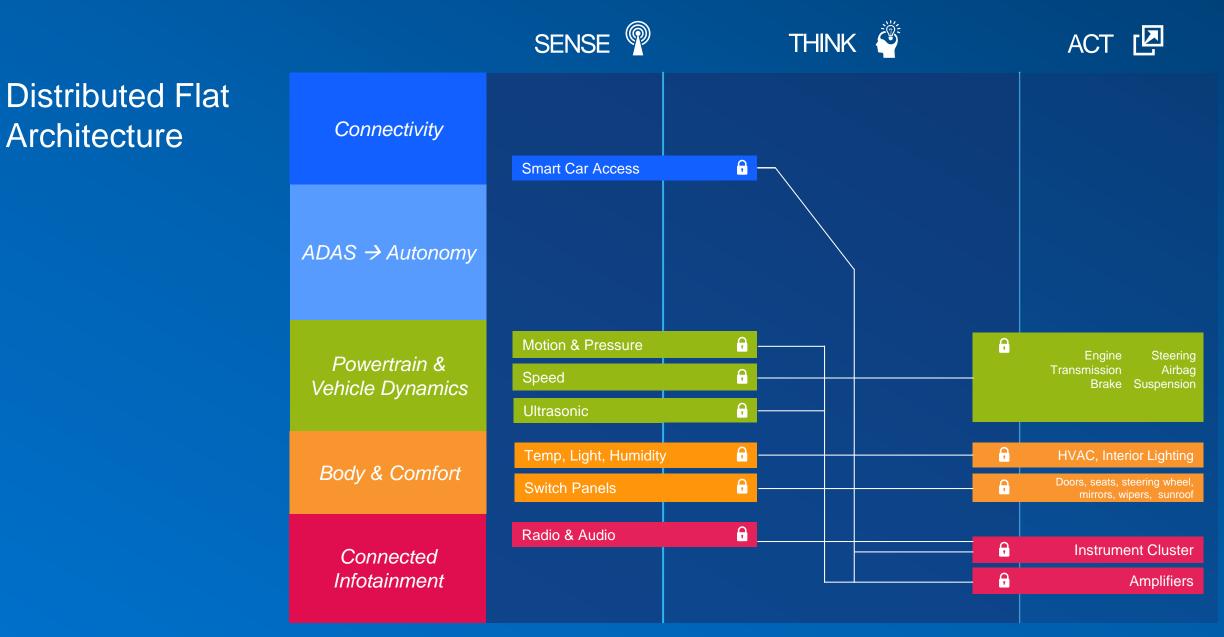
Agenda

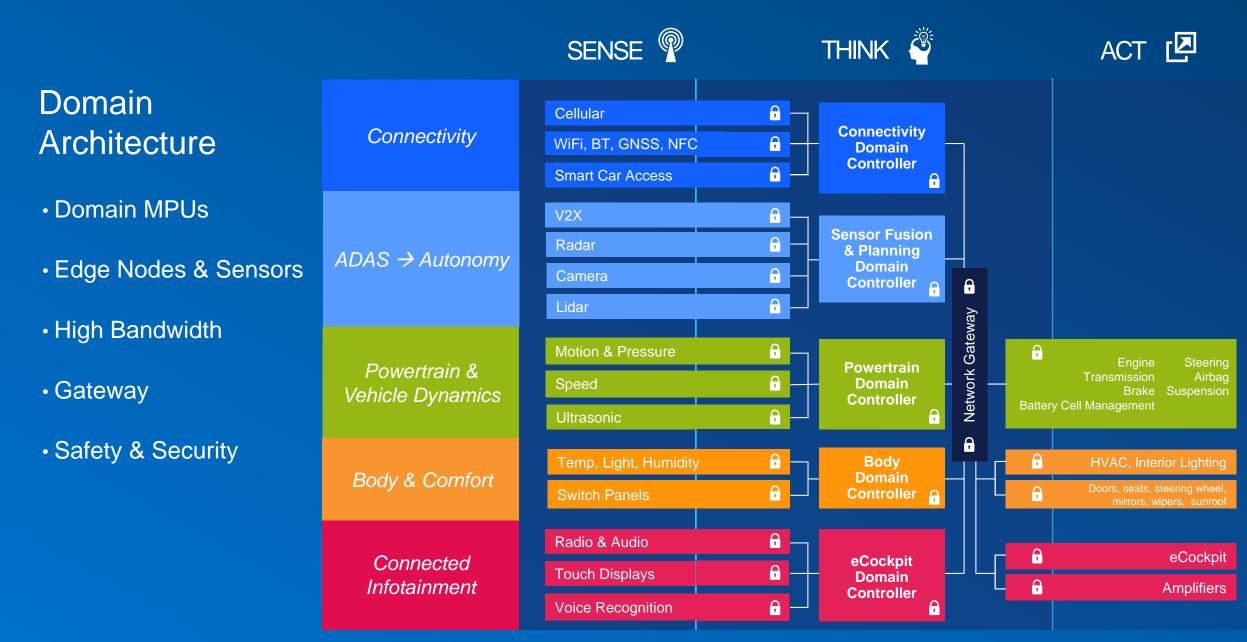
AUTOMOTIVE - SAFE, SECURE MOBILITY

Megatrends Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

- ADAS → Autonomy
- Connected Infotainment
- Network Infrastructure
- Electrification
- Summary







NXP Leads Transformation to Domain Architecture¹

Market requirement NXP unique differentiators Leveraging scalable embedded compute platforms across NXP **High Performance Domain Computing** • Deep domain specific applications know-how Auto network processing / gateway #1 leadership Secure Network Digital networking leadership Processing CAN/ LIN/ FlexRay #1 leadership Scalable & Secure Dedicated automotive Ethernet **Network Architecture** Industry leading functional safety (ASIL D) Safety and Security Complete hardware & software security

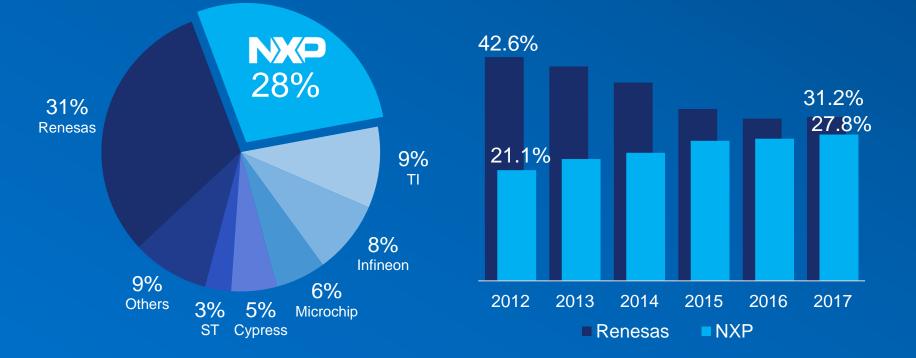


Auto Processors Today – NXP Races Towards #1 Position¹

2017 Auto Processor Market

NXP Consistently Gaining Share

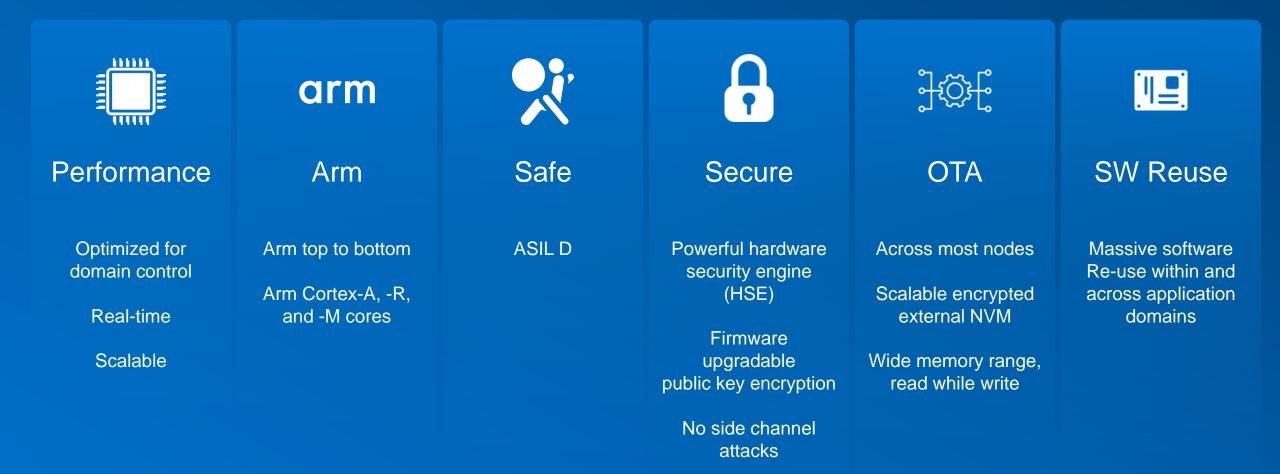
Leadership



5 years of continued market share gain

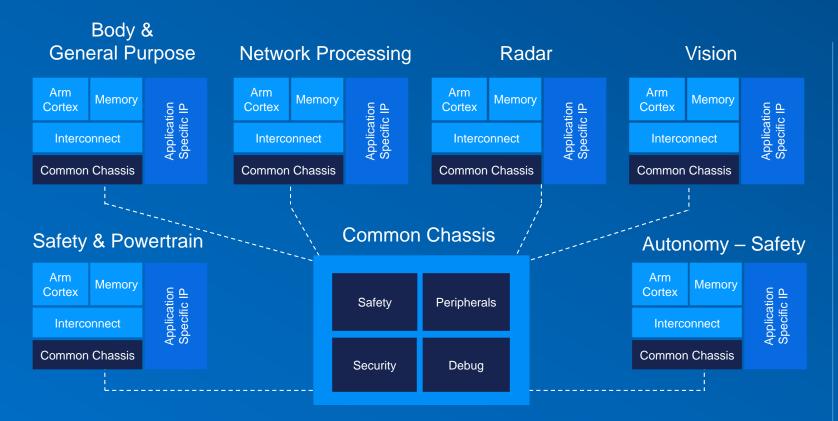


Auto Processors Tomorrow – Domain Architecture Requirements





Auto Processors Tomorrow – NXP's Unique S32 Platform



The World's First Fully Scalable Safe Auto Compute Platform Unprecedented Design Win Pipeline \rightarrow 1.5x of Previous Generations

Reduces SW R&D¹ by 35% Unified HW with identical SW environment

10x the Performance²

Multiple real time OS ADAS AI accelerators

Safe and Secure

4 independent ASIL D paths HW security engine Ready for OTA



Agenda

AUTOMOTIVE - SAFE, SECURE MOBILITY

Megatrends Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

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Servicing Variety Of Customer Requirements

DAIMLER

Established Tier-1s

System competence, scale, quality, logistics



Global support Zero defect quality Component innovation



Established OEMs

Vehicle level innovation, consumer focus

New Entrants

Speed, cost, competence from other industries

System level R&D Cross-industry insights Architecture innovation

ΤΟΥΟΤΑ

RENAULT NISSAN MITSUBISH

Integration support Auto domain knowledge System solutions & ref designs





Addressing Customer Requirements with System Solutions



Connected Infotainment Up to \$50 NXP content per car for premium infotainment system



Electric Vehicle Up to \$180 NXP content per car battery management

ADAS->Autonomy Up to \$360 NXP content per car for L4-5 imaging radar





Vehicle Infrastructure Up to \$45 NXP content per car network Infrastructure



Driving System Innovation with OEMs¹

Strategic Innovation Alliance of Strong Partners

Join innovation on system level tomorrow

V2X and Platooning Connectivity

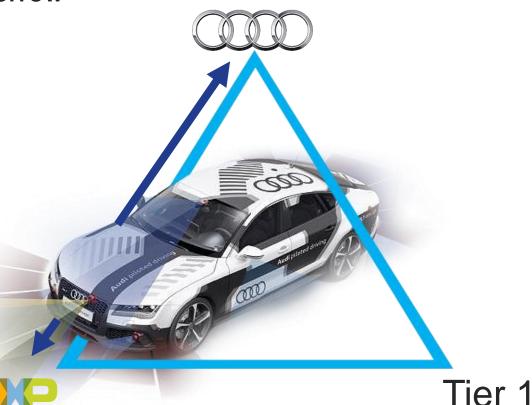
Radar platforms for high res and short range Driver Replacement

Battery management Powertrain & Vehicle Dynamics

Next generation car access Body & Comfort

Next generation car radio platform: AM robustness for e-vehicles In-vehicle Experience

Central gateway 3.0, micro server, future car architectures Secure Gateways & Networks





Agenda

AUTOMOTIVE - SAFE, SECURE MOBILITY

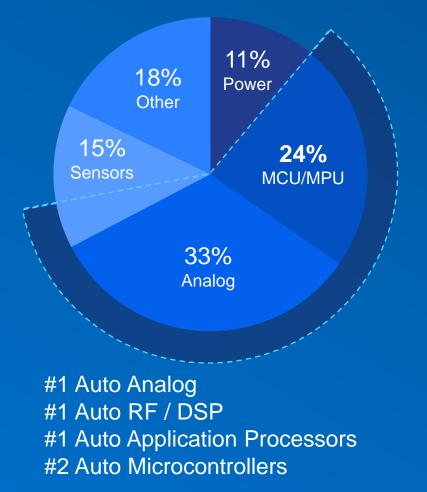
Megatrends Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

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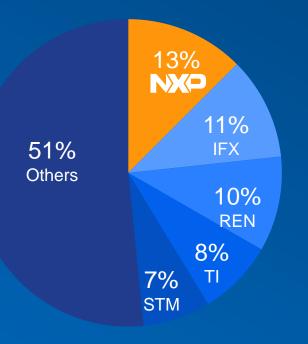


NXP Auto Leadership^{1,2,3}

Technology Leadership



Domain & Market Leadership



#1 Global Auto Semi 2017 (2017 NXP auto revenue excludes former standard products auto business)

TAM 2017: \$34.5B

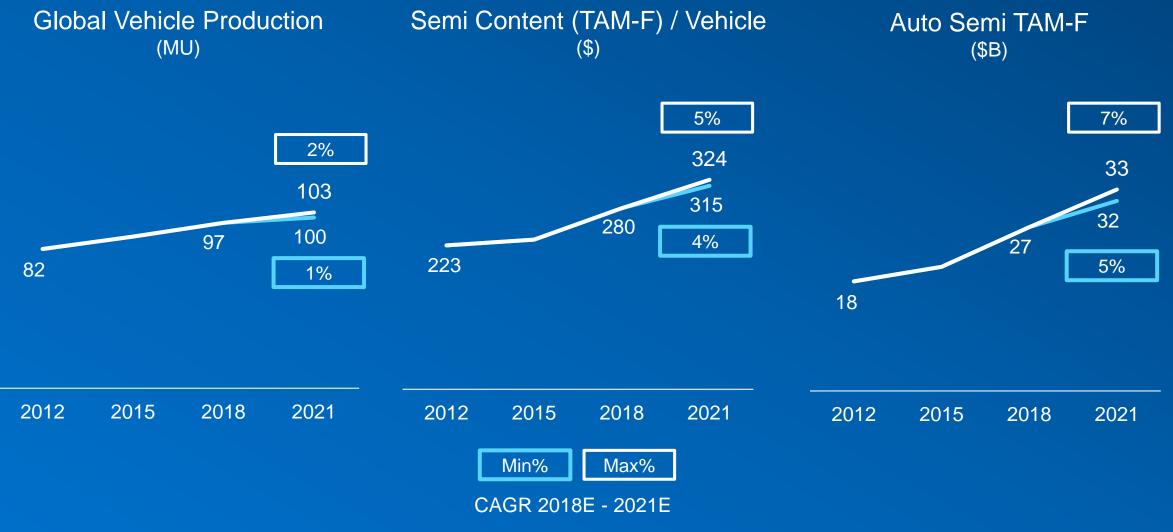


Based on 2017 Auto TAM
 Auto RE/DSP includes Secure Car Access

2. Auto RF/DSP includes Secure Car Access, Radio/Audio, V2X and Radar Transceivers

116 2. Auto Kr7DSP includes Secure Cal Access, 3. Source: Strategy Analytics, IHS Markit, NXP

Auto TAM-F Growth 5-7% – Driven By Semi Content





Leadership Across Vehicle Domains^{1,2,3}

	Connectivity	Radar (ADAS → Autonomy)	Powertrain & Vehicle Dynamics	Body & Comfort	Connected Infotainment	Secure Networks & Gateways
Focus Market Size, 2018	\$0.6B	\$1.2B	\$4.8B	\$2.0B	\$3.2B	\$1.5B
Focus Market Growth 2018-2021	9%	19%	5%	5%	5%	16%
Focus Market NXP Rank, 2018E	#1	#1	#1	#1	#1	#1
Focus Market Relative Market Share, 2018E	~2.5	>1	~1.5	>1	~2	>3
OEMs		长安汔车 CHANGAN ™ DAIMLER	CHAYSLER ANTOMOSILES GEELS	HONDA		
Tier 1 Customers		PTIV∙ (0) ⊜BOSCH	ntinental 🦄 на	LEAR CORFORATION LEAR	Panasonic BIS <u>Valeo</u>	Visteon

1. Focus Market: TAM-F for Radar & Infotainment; NXP SAM for others

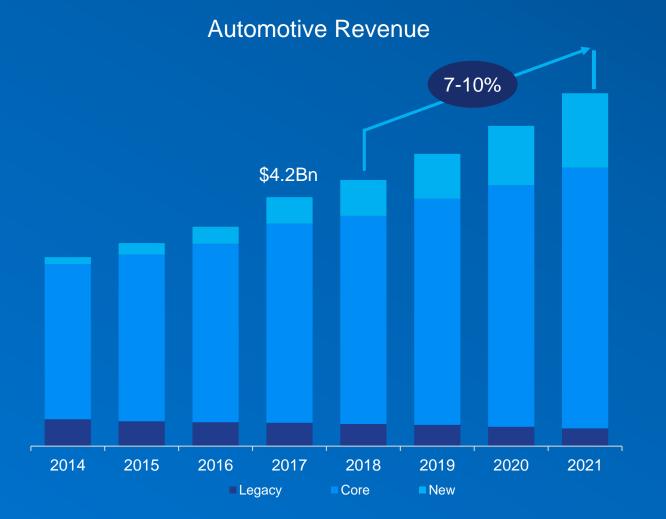
2. Includes Powertrain, Chassis & Safety MCUs, Airbag & Braking ASSP, BMS, (x)EV MCUs, Magnetic & MEMS Sensors

118 2. Includes Powertrain, Chassis & Safety MCC 3. Connectivity focuses on secure car access



Consistent Broad Based Growth¹

Accelerated by select new high growth applications



	CAGR '18- '21	Key Applications
New	20-28%	 Radar Network Processing + Ethernet Electrification ADAS Vision, Fusion, V2X
Core	6-8%	 Connected Infotainment Powertrain & Vehicle Dynamics General Purpose MCU Network Transceivers Secure Car Access
Legacy	(7-8%)	• 8 bit MCU • Other



Agenda

AUTOMOTIVE - SAFE, SECURE MOBILITY

Megatrends Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

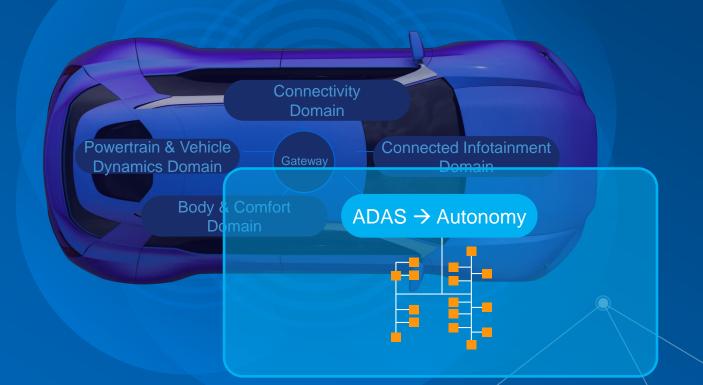
- ADAS
 → Autonomy
- Connected Infotainment
- Network Infrastructure
- Electrification
- Summary



ADAS → Autonomy

Torsten Lehmann

Senior Vice President & General Manager





Increasing Autonomous Driving Levels Push ADAS \$ Content

5

Semi Content Potential per Vehicle vs Level 0 in 2020



New Entrants Straight to Level 4/5

- Mobility operators start autonomous services 2019
- 1% of semi opportunity '21 (~15% in '25)

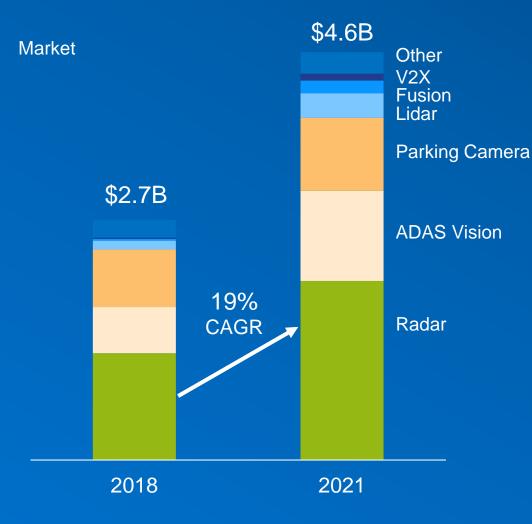
Traditional OEMs Increasing ADAS value

- Regional NCAP rating pushes Level 1/2
- Further automation (L3/L4) as OEM differentiator
- In 2021 99% of semi opportunity in Level 1-3



Automation Multiplies Sensors and Silicon Content In Development **New Entrants** In Production Level 3 Level 4/5 Level 1/2 \$100-\$150 \$600 \$900-\$1200 Silicon Value Silicon Value Silicon Value units units units Radar 1-3 Radar 4-6 Radar 6-10 Camera Camera ≥4 Camera 6-8 1 Lidar Lidar 0-1 Lidar 1-3 V2X V2X 1-2 0-1 V2X Fusion Fusion **Fusion** 1 <u>Lidar</u> 24GHz Radar 77GHz Radar **Fusion** V2X Camera

Radar: Largest ADAS Segment With Top Value Growth¹²



Radar

- Represents ~44% of ADAS TAM-F
- NCAP safety ratings drive penetration
- 360° view & imaging radar drive semi dollars

Other ADAS

- ADAS vision is NCAP driven
- Parking cameras maturing
- V2X: Volume car ramp starting 2019 with VW



NXP Strongly Positioned with Broad ADAS Play

ADAS Expected to Exceed 10% of NXP Automotive Revenue by 2019



Radar

- #1 Leader, design wins at 10 of top 10 OEMs
- Major new wins with RFCMOS at 7 OEMS

🚔 🕷 🛱

Leader: Modem, Processor, SW, Security

 In production with GM, ramping at VW 2019 "We trust NXP's V2X leadership & innovation that enables us to improve road safety by launching V2X as standard feature in volume cars from 2019. Dr. Alexander Graf, Connected Car, Volkswagen AG

ADAS Vision

 Safe automotive vision SoC Partnerships with leading tier-1s



- Safe processing with AI
- Working with 5 Lidar leaders



System Selling

- Full solutions adding \$ value
- Networking & power management



Parking Camera

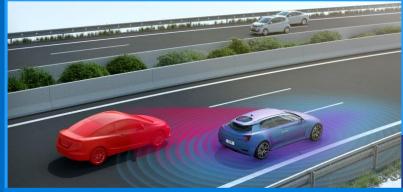
- Safe processing & machine learning
- Designed in at >10 major OEMs

Fusion and Central Processing

- Safe processing with integrated AI capability
- Leading MIPS for automotive safety (ASIL-D)

Radar: Triple Acceleration for Semiconductor Value

More cars with radar NCAP safety



+

Blind spot detection Automatic emergency brake More sensors per car 360° radar cocoon



Front & rear cross traffic / people detection

More ICs & higher value per sensor High resolution 360° imaging

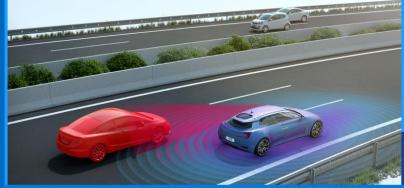


Precise environment map and localization



Radar: Triple Acceleration for Semiconductor Value





More sensors per car 360° radar cocoon



×

Front & rear cross traffic / people detection

More ICs & higher value per sensor High resolution 360° imaging



Precise environment map and localization

Blind spot detection Automatic emergency brake



Radar: Taking Safety to New Levels – Saving Lives

Full 360° surround view small & low power sensors

Precise Environmental Map e.g. curbstones & pylons in distance



		NXP full performance span				
Bulky	24GHz	77 GHz	Multiple 77 GHz	Small		
High Power	SiGe	RFCMOS				
Low Res	Radar processing <1 GFlops	Advanced object detection 15-20 GFlops	Imaging Radar >350 GFlops	High Res		
		NXP Investment Focus				

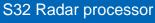
Radar: NXP's Unique Scalable Full System Solutions

Full 77GHz System Solution

Full Performance Span

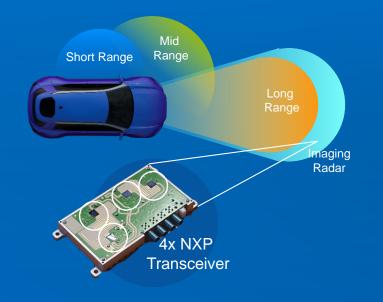
RFCMOS Transceiver



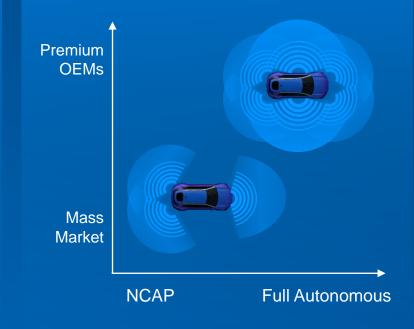


Power Management

Ethernet



Winning Across All Segments



- Full reference design
- Plus Software Development Kit
- Plus Functional Safety

- SiGe & RFCMOS transceiver portfolio
- Scalable processor families
- From simple sensor to imaging radar

- Designed in with all top 10 OEMs...
- ...while also growing with new players
- System solutions for China (e.g. **GEELY**)





3 More ICs & higher value per sensor

130 1. Source: IHS Markit, NXP CMI

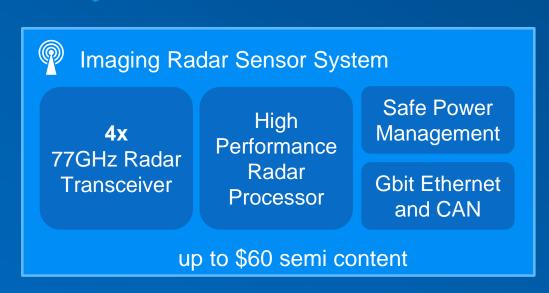


Imaging Radar: Next Wave of Growth with L3-L5 Autonomy



Up to \$360 Semi content per vehicle

- Imaging radar approaching Lidar-like resolution
- Capture precise environmental map
- Outperforming Lidar in adverse weather / light conditions





Processing: Further Growth by Enabling Safe Autonomous Driving

Safe Computing Leader New Safety Applications

Decade of experience Broad OEM adoption

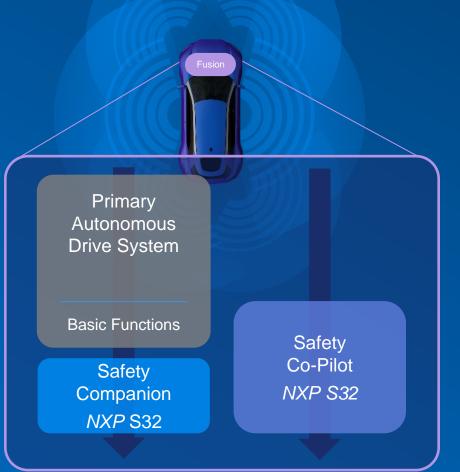


Safety Companion

Safety checker and safe communication to vehicle (ASIL-D)



Safety Co-pilot Validate decisions & provide fail operational backup

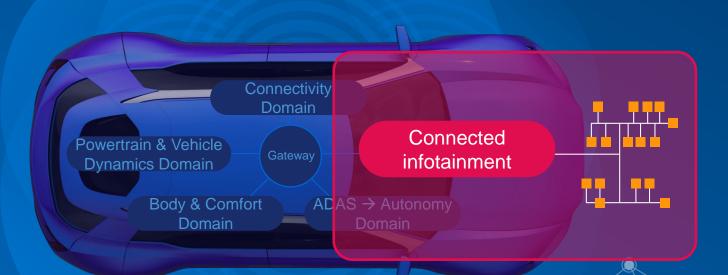




Connected Infotainment

Torsten Lehmann

Senior Vice President & General Manager



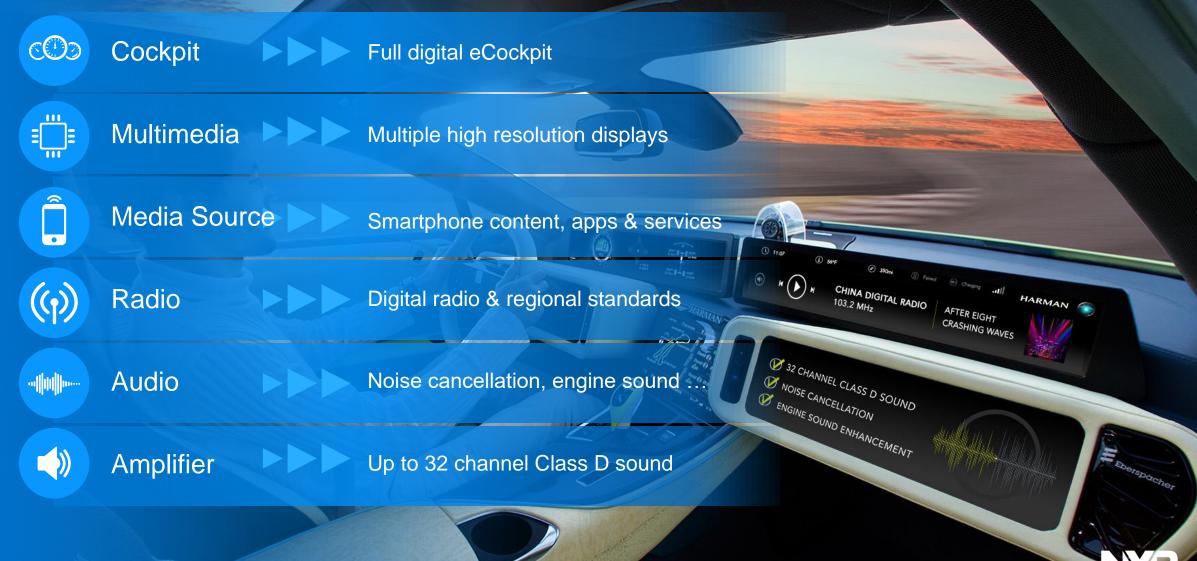


Increasing Consumer Expectations Drive Infotainment Growth



Connected Infotainment: Key Differentiator & Sales Driver for OEMs

STRAHLE+ HESS



Winning in Connected Infotainment with Full System Solution



Key Growth Drivers for NXP Connected Infotainment

eCockpit Drives Display Count Increasing Audio & Digital Radio

Major Growth with Systems in China



SoC Value



Radio & Audio \$ Per Car

Outgrowing Global Infotainment

- i.MX8: driving up to 4 screens
- Value beyond the product: quality, supply, enablement & partnerships
- Digital radio 1-chip drives adoption
- More NXP audio value: noise cancellation, engine sound, 5.1 etc.
- Full infotainment system solution & ecosystem accelerating customers
- Supporting China digital radio launch



Customer Success Confirms NXP Market Traction

eCockpit Drives **Display Count**

Increasing Audio & **Digital Radio**

Major Growth with Systems in China





- Design in with 2 of top 3 US OEMs
- Record level i.MX awards last 2 years
- eCockpits with i.MX8 shipping 2019

- NXP in ~30 car brands with Harman
- Amplifiers in premium car sound brands:

Marht→

HRI. BANG & OLUFSEN

harman/kardon[®]

Bowers & Wilkins

"Our long-term partnership helps us to provide industry-leading solutions and new infotainment experiences to our customers." David Slump, EVP Operations, Harman

Alios

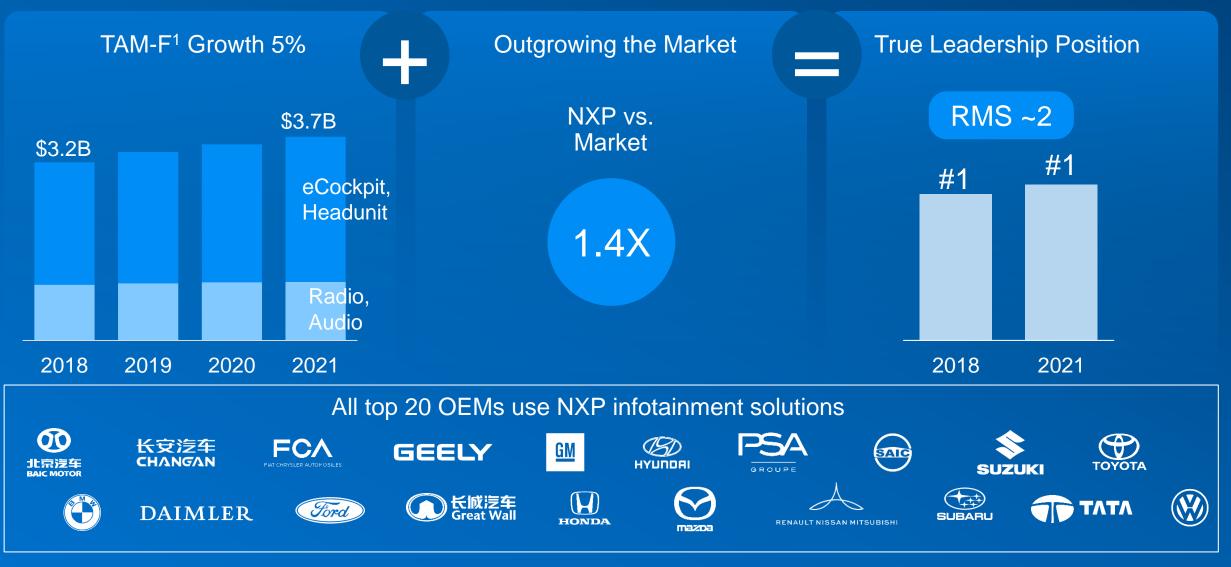
Autmotive OS by Alibaba Group

- Full NXP portfolio: i.MX, radio, audio
- Two major China OEMs won
- AliOS: Supporting China Digital Radio

"We look forward to redefining the future of the automobile sector in collaboration with our infotainment semiconductor partner NXP." Gary Wang, General Manager, AliOS



#1 Leader for Connected Infotainment



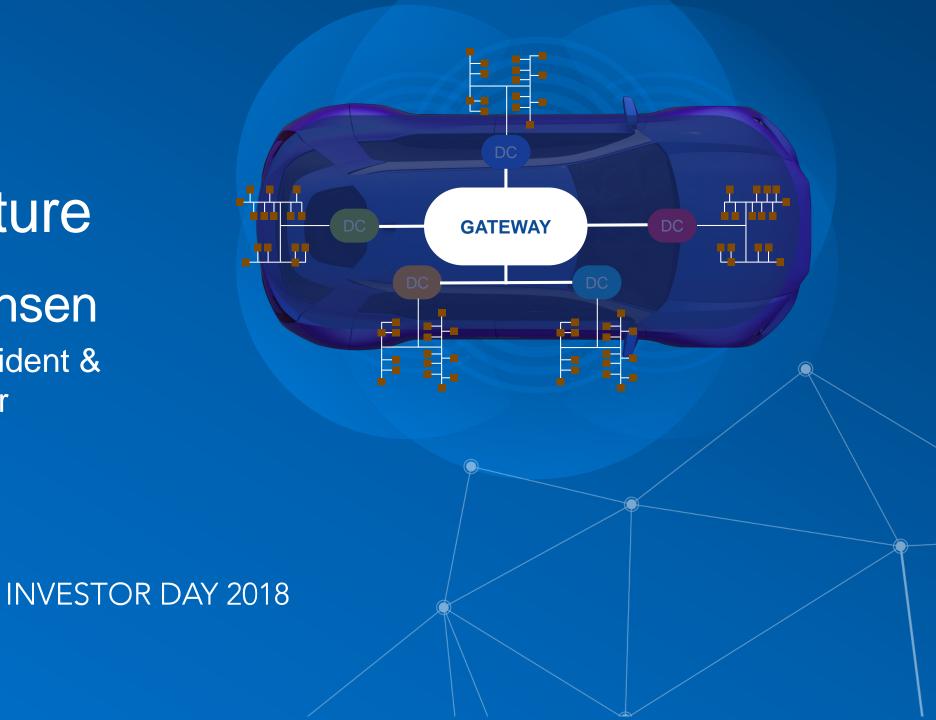


139 Source: Strategy Analytics, NXP CMI 1. Excludes Device Connectivity, Cellular Chipset and GPS Location

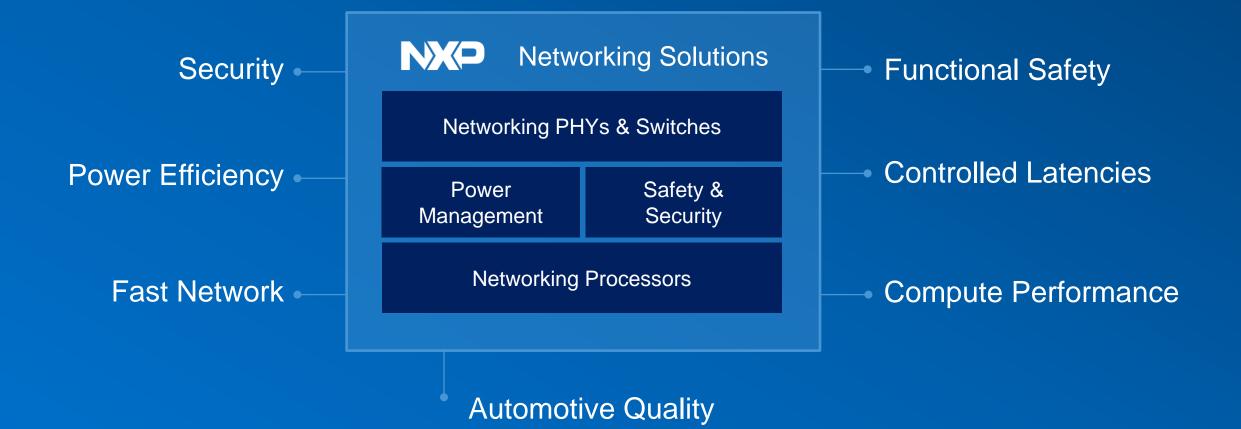
Network Infrastructure

Jens Hinrichsen

Senior Vice President & General Manager

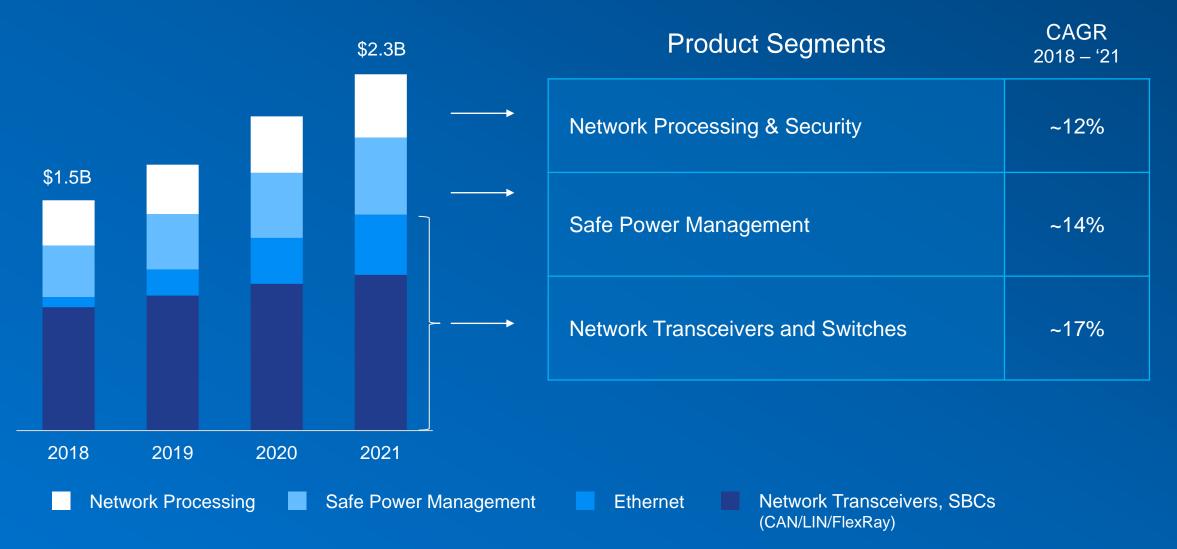


New Architectures Drive Advanced Networking Requirements Up to \$45 NXP content for car network infrastructure

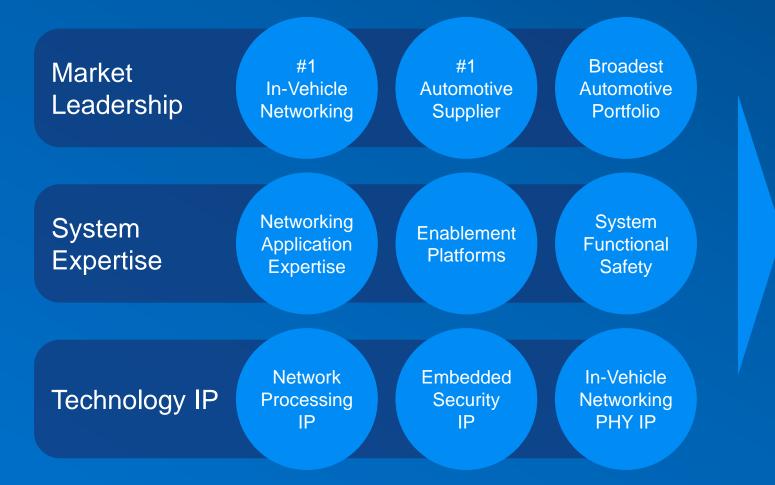




Automotive Networking Market Growing at 16% CAGR



NXP Leads in Providing End-to-End Networking Solutions



- OEM focused go-to-market
- Trusted advisor role
- Faster innovation cycles
- Inherent security & safety



Leadership in Network Processing for ADAS Vehicles



End-to-End Networking Solution

- By 2025 majority of all new cars will have a central gateway
- Network processing enables end-to-end security, over-the-air upgradeability and revenue-generating services



Leadership in In-Vehicle Networking Interfaces

NXP Portfolio **Covers all Standards**

Networking Growth

NXP Focus

\$/Vehicle Connectivity Ψ Fast Gbps **Connected Infotainment** ADAS -> Autonomy Secure 100 Mbps FlexRay 10 Mbps Smart Powertrain & Vehicle Dynamics Robust 1-5 Mbps Body & Comfort 20kbps 10-20 20-50 50-100 Nodes/Car

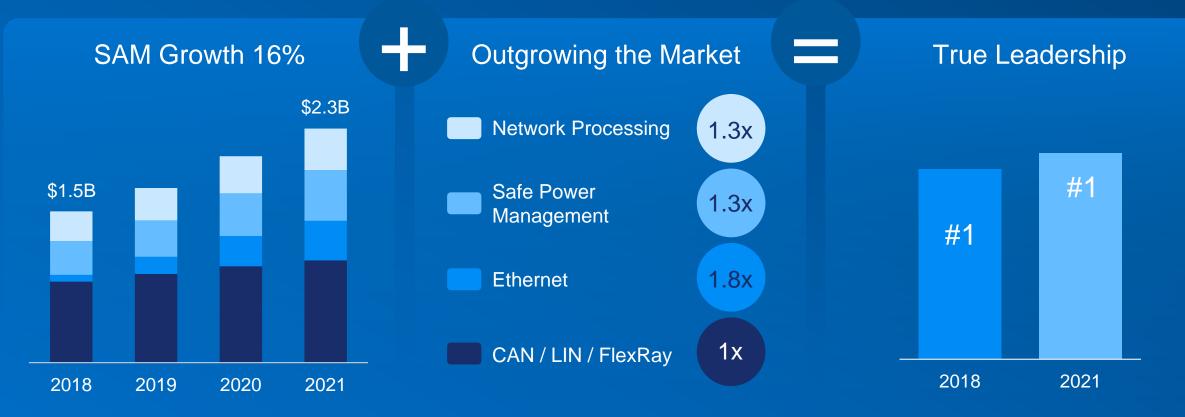
Complementary Major Networking Standards

- True automotive robust Ethernet solutions
- Lead standardization of multi-Gbit Ethernet
- Launch high-speed **CAN FD solutions**
- Introduce SecureCAN •



Data rate

Expand Leadership Position in Automotive Networking



- NXP defines next generation vehicle architectures with OEMs as trusted advisor
- NXP won all major 2021+ gateway processor platforms
- NXP outgrows Ethernet market, defines multiple-Gbit automotive Ethernet PHY standards

NXP Automotive Networking Key Strategic Moves

NXP Digital Networking business boosts Automotive Network Processing Leading Ethernet & SerDes IP provider mniPHY becomes part of NXP

Extend lead in automotive networking

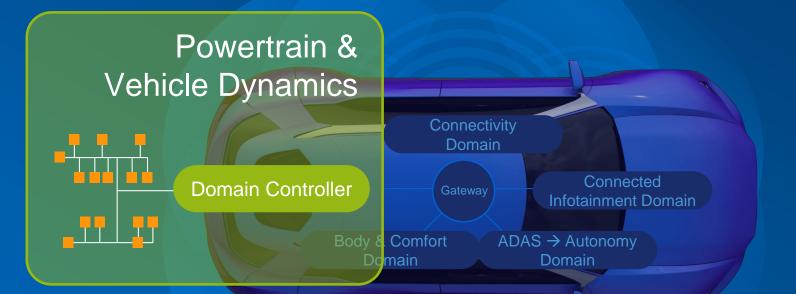
Define next generation network processors and secure Ethernet solutions



Electrification

Jens Hinrichsen

Senior Vice President & General Manager



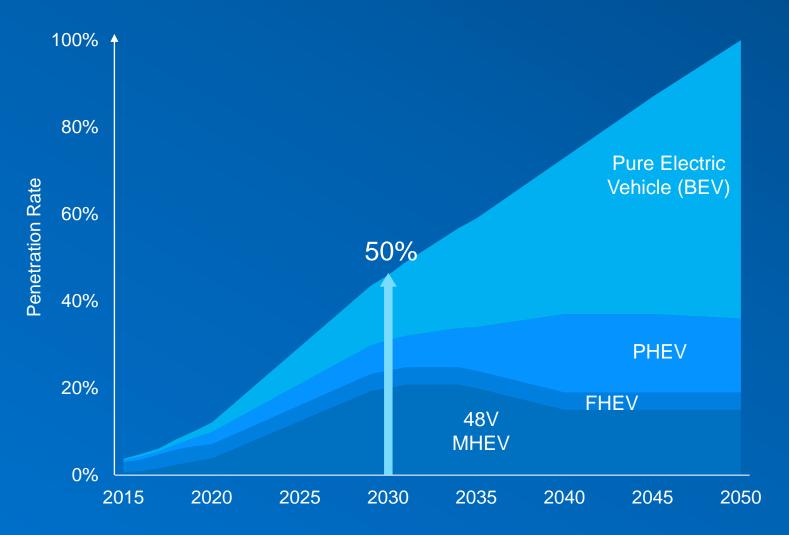


Electrification of Powertrains Boosts Semiconductor Content

Types of Powertrains	Combustion Engine (ICE)	Mild Hybrid (MHEV)	Full Hybrid (FHV)	Plug-in Hybrid (PHEV)	Range Extended EV (REEV)	Battery Electric Vehicle (BEV)
Combustion Engine	••••	••••	•••	•••	$\bullet \bullet$	
Battery System	 [+]	 [+] [48V_]	 [+] [+] [LV_] [HV_]	 [+] [+]	 [+] [+] [+_V_]	 [+_v_] [+_v_]
Mains Charging	-	-	-	₽	ل الج م	گ ر ۲
Electric Traction	-	〔 三 〕 10 – 20kW	[] 15 – 60kW	40 – 80kW	40 – 80kW	> 80kW
Added Semiconductor Value	-	+\$200	+\$350	+\$400	+\$425	+\$450



Accelerated Growth of Electrified Vehicles

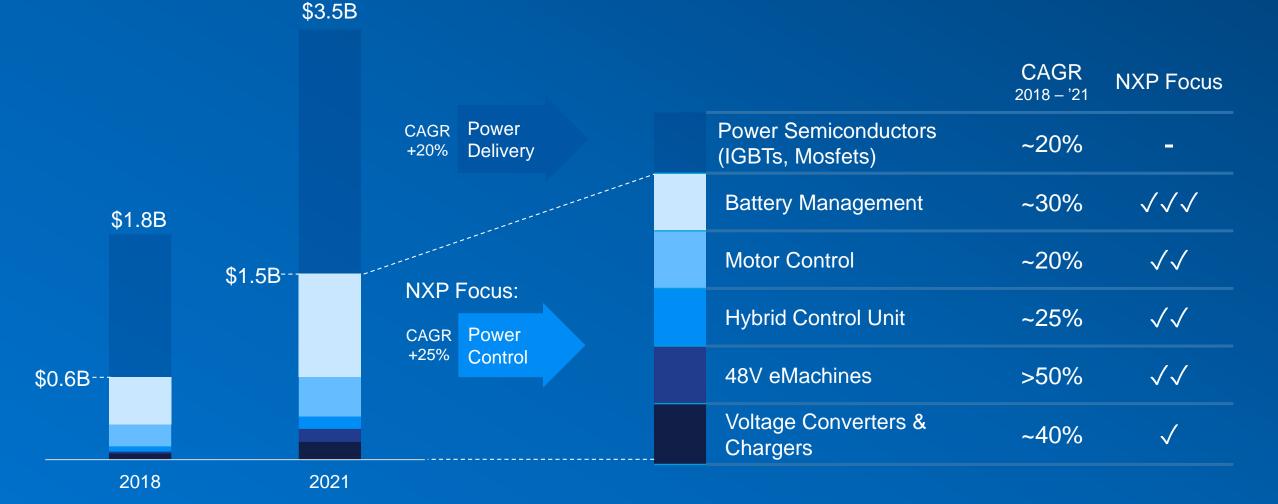


- 2030: ~50% of all vehicles sold contain electrified powertrains
- Dynamic market environment with emerging (xEV) OEMs
- China major market driver
- Europe leading in 48V hybrid



NXP Focuses on Power Control

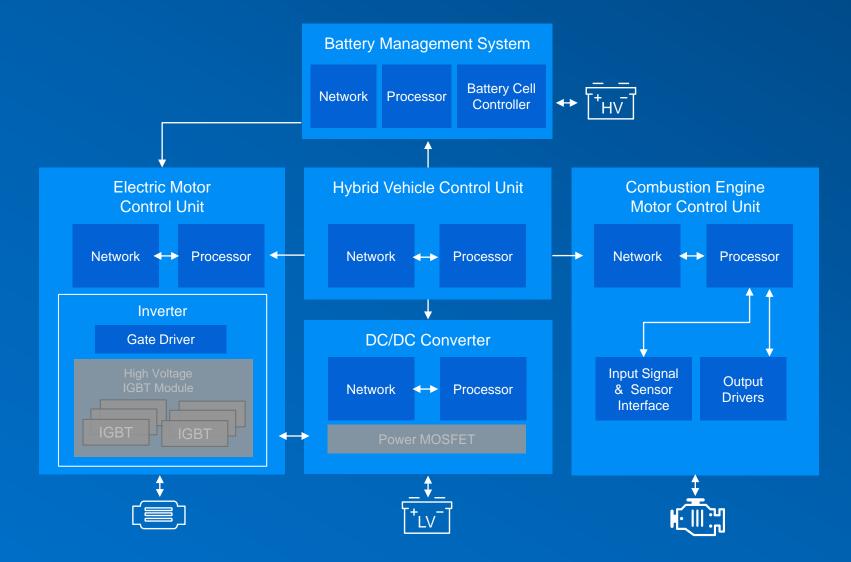
NXP addresses 40% of electrification TAM growing at 25% CAGR



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NXP Provides Leading Powertrain Control Solutions

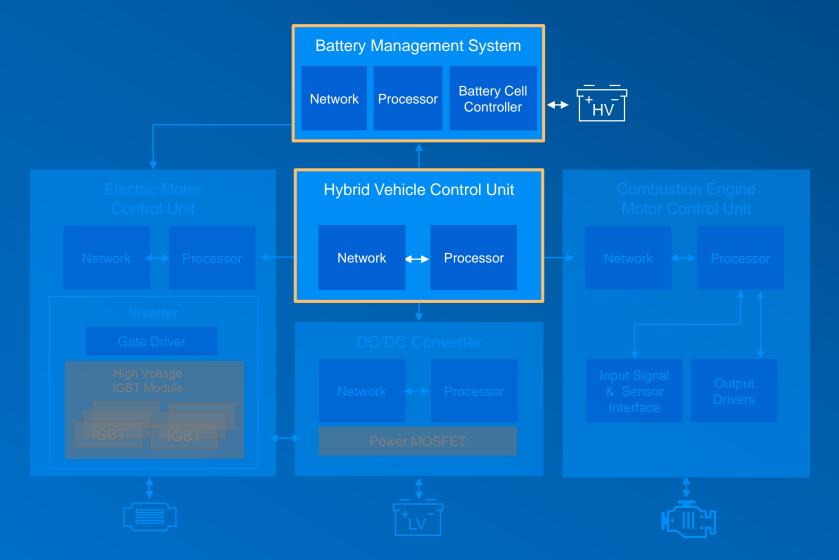
System optimized, scalable, secure and safe





NXP Provides Leading Powertrain Control Solutions

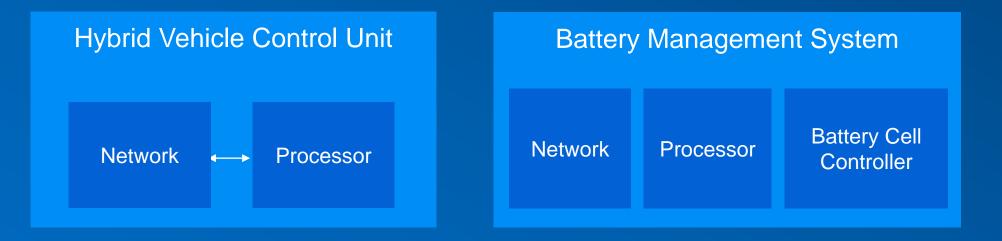
System optimized, scalable, secure and safe





NXP Provides Leading Powertrain Control Solutions

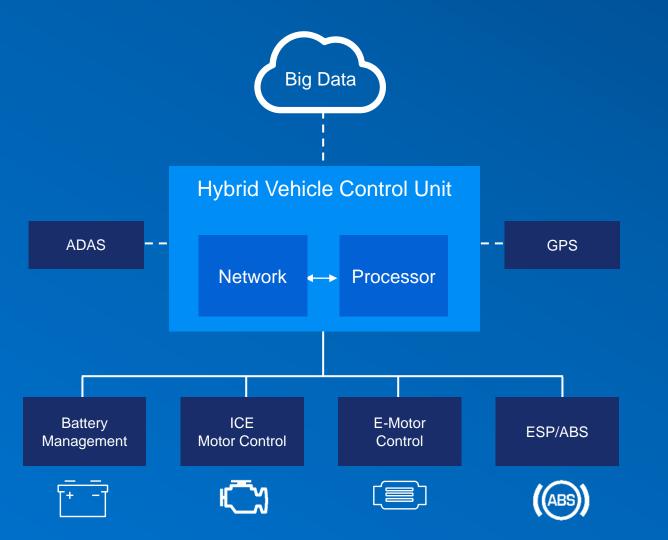
System optimized, scalable, secure and safe





NXP S32 Enables Advanced Hybrid Control Units

Multicore high end processor with dedicated motor control and security peripherals



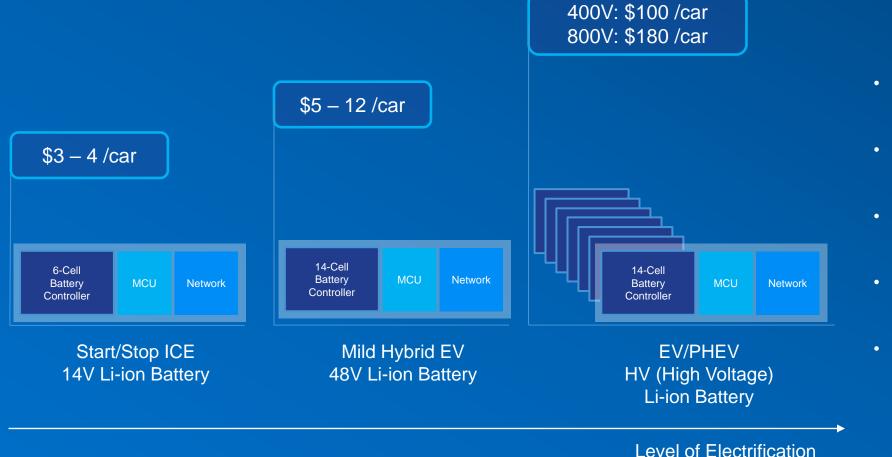
Optimize energy use Trip optimization (ADAS & GPS) Life time optimization (Analytics & AI) Greenbox development platform

Development platform for S32 safe and secure processors





NXP Battery Management Scalable Across All EV Powertrains



- Leading accuracy
- Fast & robust communication
- Highest BOM integration
- Hardware/software scalable
- ASIL-D functional safety

NXP on Path to Leadership in Battery Management



- Won key high-voltage HEV and BEV platforms from leading German, Chinese and US OEMs
- Won > 80% share in worldwide 14V & 48V MHEV platforms
- Partnering with globally leading battery makers



Agenda

AUTOMOTIVE - SAFE, SECURE MOBILITY

Megatrends Tech Leadership: Domain Architecture Customer Leadership: System Solutions Growth

- ADAS → Autonomy
- Connected Infotainment
- Network Infrastructure
- Electrification
- Summary



Auto Growth: Broad-based + Select High Growth Drivers

2018–2021 3-Year CAGR

NXP Auto Revenues	7-10%
Auto Semi TAM-F	5-7%
Content / Car	4-5%
Car Production	1-2%

Growth Drivers on Top of Core Business

1	ADAS: Radar
2	Infotainment: e-Cockpit + Radio & Audio
3	Networking: Gateway + Network
4	Electrification: Battery Management



NXP Auto Value Proposition







Solution Portfolio

Complete system solutions for fastest TTM

Innovation Power

In-house high performance processing and networking

Safe and Secure

Leading with security and functional safety

Trusted global automotive partner: excellent quality, reliability, supply





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Go to Market

Steve Owen Executive Vice President Sales & Marketing





Our Sales Engagements Have Become Stronger Over Past 21 Months







Strengthened our OEM connections while shaping new ecosystems Leverage the Distribution Channel as a force multiplier (> 26k Customers) World class customer technical support as a differentiator







WELCOME TO CGTN.COM

China World Politics Business Tech & Sci Culture & Sports Opinions Picture

Dutch chip giant NXP expanding business in China



TECHNOLOGY By He Weiwei, Huang Yi, and Li Jun ① 2018-09-07 17:40 GMT+8

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NXP, a chip giant from the Netherlands, announced plans to work with a variety of Chinese tech brands at a recent tech summit in Shenzhen, south China's Guangdong Province.

GLOBAL

or more news, downlo

NXP, a chip giant Chinese tech brai Province.

The world's largest supplier of automotive semiconductors currently works with major Chinese companies like Baidu, Geely and Xiaomi. It's new partnerships include IrisKing - an iris recognition technology developer, Hangsheng Technology – an automotive supplier, and Foxconn Industrial Internet - a communications network equipment manufacturer

The world's large By He Weiwei, Huang Yi, and Li Jun QR

Chinese companies like Baidu, Geely and Xiaomi. It's new partnerships include IrisKing - an iris recognition technology developer, Hangsheng Technology - an automotive supplier, and Foxconn Industrial Internet - a communications network equipment manufacturer.



NXP, FII partners on IIoT

Ninelu Tu, Taipei: Joseph Tsai, DIGITIMES 🕘 Friday 7 September 2018 🛸

NXP Semiconductors will provide Foxconn Industrial Internet (FII) with its iIndustrial I and tachnical support., according to an MOU signed on behlaf of their repesctive com bal Sales & Marketing Steven Owen and FII's vice president Vincent Chen.

two firms will jointly develop an IIoT platform to help manufacturers implement te innovated business models.



NXP eyes IOT, smart vehicle opportunities

The move is part of broad- spur demand for chips. The such a system by 2020 er deals NXP has inked with opportunities in China are The company has also se Chinese companies includ- pretty strong given that local up an application center in NXP Semiconductors, the ing the one with Iris Recogniworld's top chip maker for the tion, a leading computer governments are keen to increasingly complex prod auto industry, is ramping up vision player at a major tech embrace autonomous and ucts, especially microproces resources to tap into the conference in Shenzhen, connectivity internet of things and smart Guangdong province recent- Owen said. vehicle opportunities in China, where local consumers are highly responsive to new technologies.

president of sales and mar- nese internet behemoth Baiketing at NXP Semiconduc- du Inc in offering safety The company announced tors, said as the trends of technologies for smart-drivon Tuesday that it has inked a connectivity, electrification, ing experiences. It has also for almost two years, partnership with Foxconn autonomy continue in the teamed up with Alibaba Industrial Internet Co Ltd, a automobile sector, the semi- Group Holding Ltd to intesubsidiary of the world's largconductor value in each car grate its in-car entertainment est contract manufacturer Foxconn Technology Group,

future from \$380 in 2017. to pursue growth in the More than 90 percent of ating system. The two sides some loss of clients for NXP industrial internet of things innovation in cars will be aim to have more than one but on the whole had limited from electronics, which will million cars equipped with impact on its products

The Dutch company has Earlier this year, the Unite Steve Owen, executive vice already partnered with Chi-States semiconductor gian Qualcomm Inc gave up it proposal to acquire NXP. deal which had been going o Lu Wenliang, an expert the research institute of Chi na Center for Informatio will be more than tripled in platforms and technologies to Industry Development, said the latter's automobile oper- the deal failure resulted in

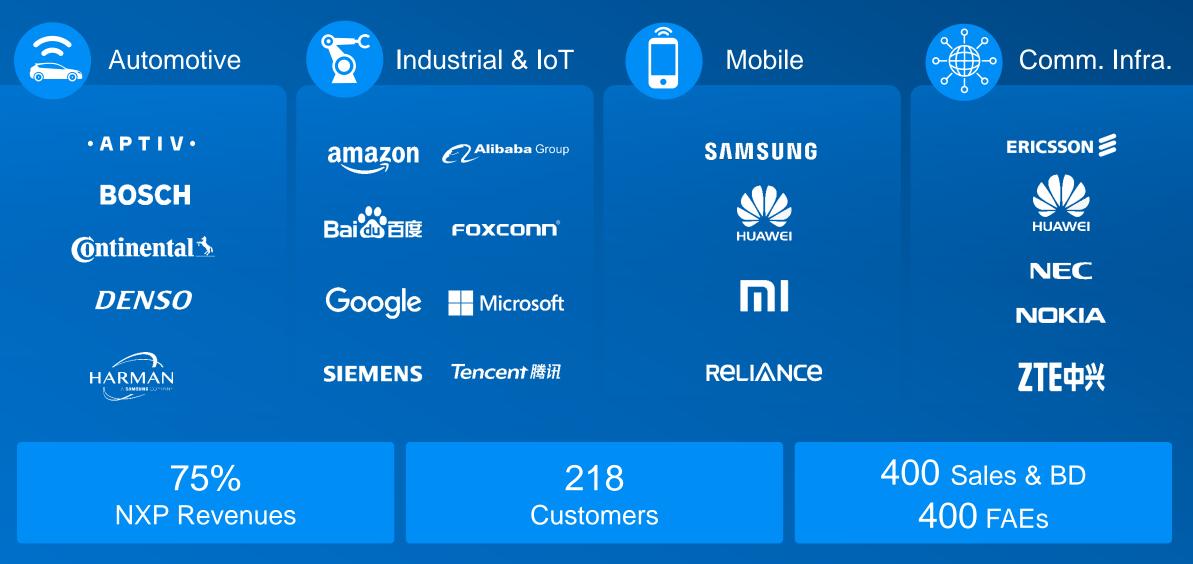
sors, can fully support loca

carmakers, consumers and Chongqing to ensure that its

technologies.



NXP Has Unrivalled Depth & Reach of Customer Access





Mass Market & Distribution as a Force Multiplier

Physical

~8000 Distribution Sales & 1100 Certified FAEs

>30 Distribution Partners

> **300** Sales and FAEs

>26K

Customers 25% NXP Revenue

Enable innovators and future leaders

Digital

Digital Portals Online Training & Communities

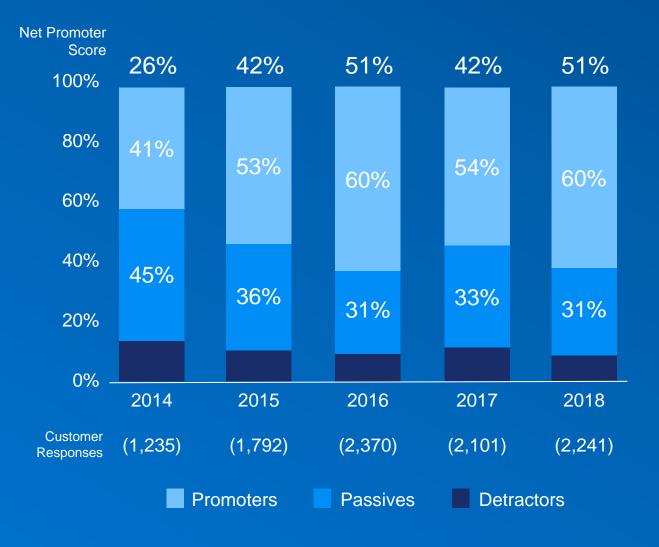
Physical & Virtual Tech Support

Complete Solutions & Reference Designs





Our Customers are Our Best Advocates¹



- 95th percentile of technology companies
- Strong correlation with employee satisfaction
- 68% active promoters in mass market

>20% Design Win growth in 2017 in focus markets, driven by

- Processing leadership
- Attach in Industrial & IoT and Automotive





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Summary and Q&A Rick Clemmer Chief Executive Officer





Since April 2016...

Automotive



Semi content \$ / vehicle accelerates

- #1 auto processors position now at reach
- Reached true leadership in infotainment AP
- Developed & captured emerging networking gateway market
- Created new electrification solution portfolio
- Achieved radar #1 leadership position
- On track for 2019 ADAS revenue >10% Auto
- V2X ramping with GM, VW in 2019, + others
- Introduced leadership S32 16nmFF

Mobile

- Shipping single chip NFC-SE
- 4000 banks supporting mobile payment
- China mobile transit from 10 to 100 cities
- IoT Service2GO

Industrial & IoT

Comm. Infra.

& Other

- IoT evolved into tangible edge & end-node opportunities to enable cloud disruption
- Grew share in GP embedded processing 9% to 11%
- Created & captured X-Over processor category
- First FinFET IoT app. processor
- Unified software platform across processing portfolio

mMIMO true leadership

- 16nmFF Layerscape
- Leveraged DN IP & expertise into Auto, Industrial IoT
- 2X RAIN RFID revenue growth



Continuing to Drive Profitable Growth



Automotive

Solution portfolio Innovation powerhouse Safety & reliability expertise



Industrial & IoT Broad, scalable solutions

Common S/W tool environment Channel reach



Mobile

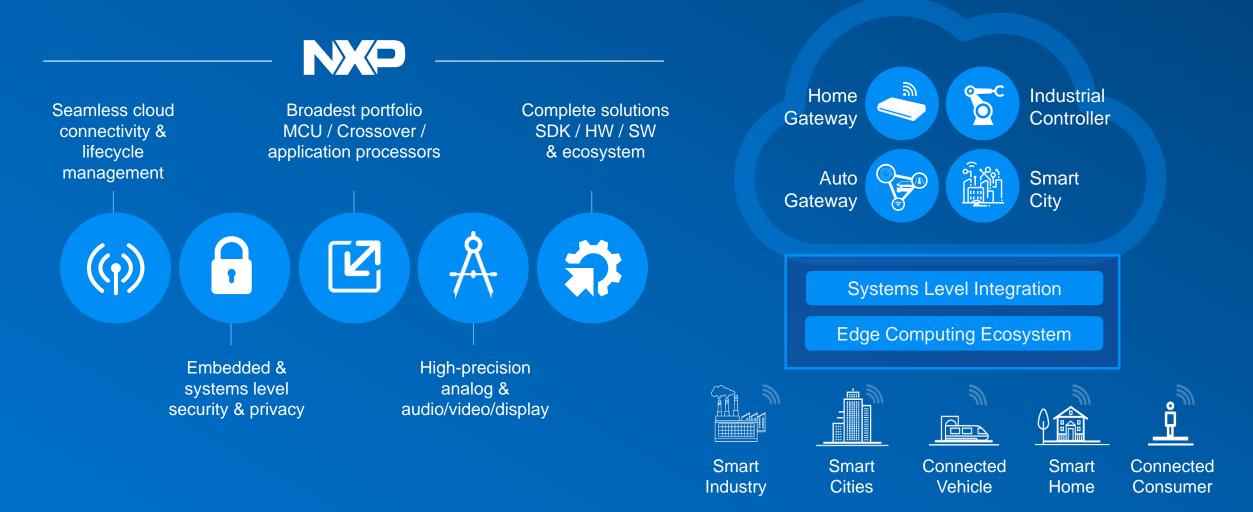
Technology innovator & leadership Recognized ecosystem leader Focused application insights



Communication, Infrastructure & Other Broadest portfolio (RF, tags) Technology leadership Deep application insights



NXP Uniquely Enables Disruptive Nature of the Cloud





Secure Connections for a Smarter World¹

Secure anchors & services for 40B processors



75% connected cars by 2025



173

Tagging 60B products per year by 2025

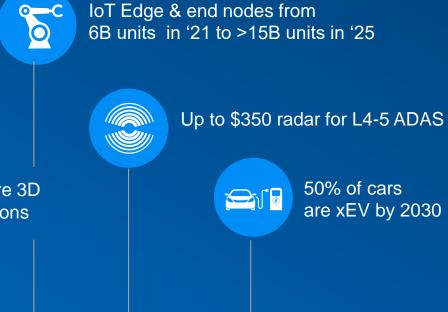
25% of cars by 2025 will be L2-3 ADAS 3x adoption rate



2B+ 5G subscribers by 2025



UWB potential: secure 3D device ranging in billions of phones & things





Value Proposition







Solutions

Core Competency



Driving RMS Leadership

Focused on RMS > 1.5X Multiple High Growth Markets

Profitable growth R

Resolving customer pain-points World-class Expertise & Team

Customer focused passion to win

Maximize Shareholder Value

Strong cash flow generation





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